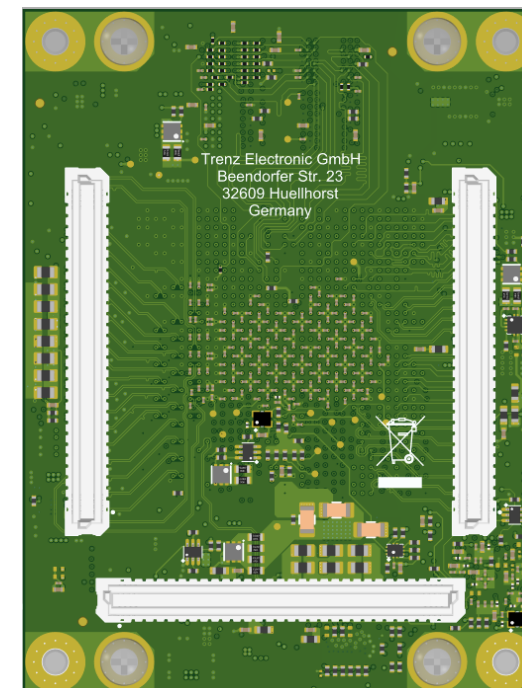
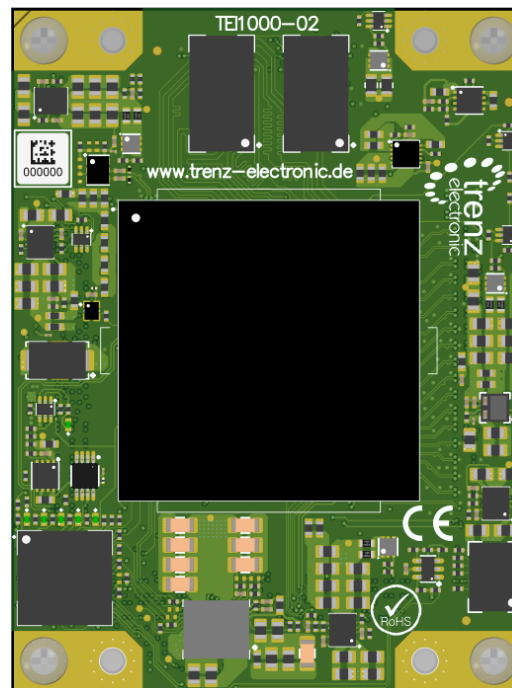
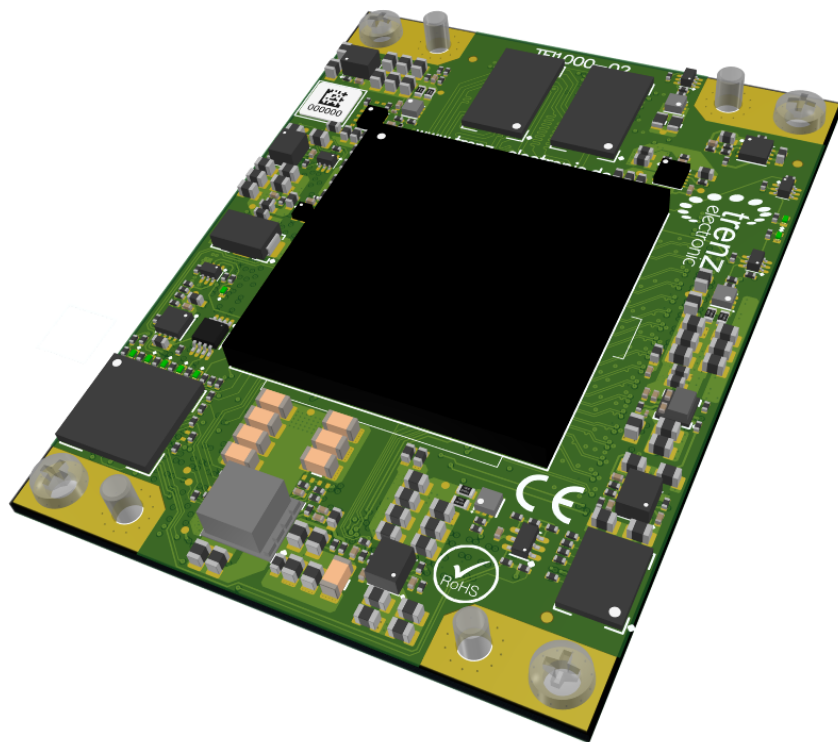


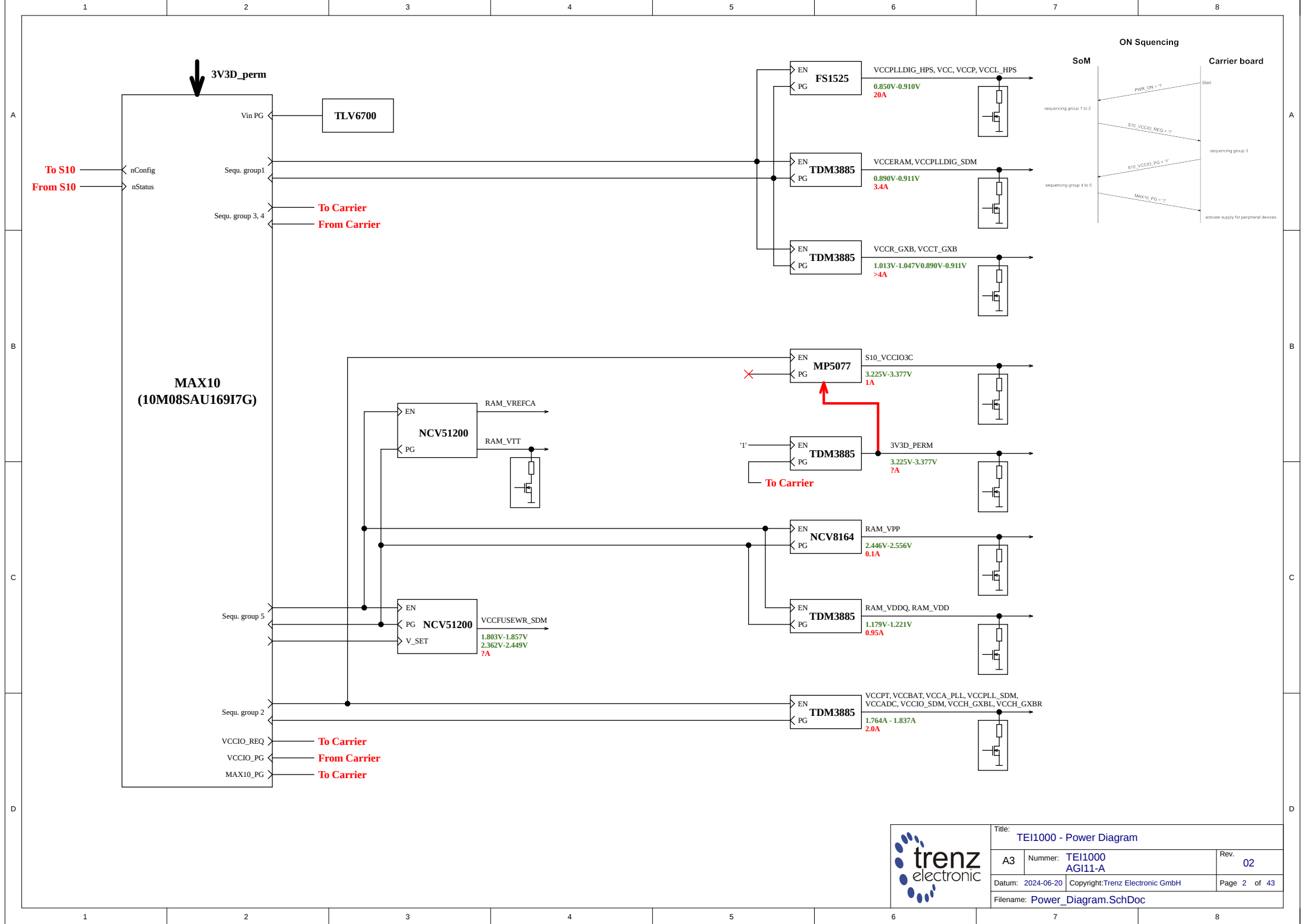


Regarding the usage of our schematics and alike documentation for Trenz module TEI1000.

Project is protected under copyright and we strongly and strictly prohibit the reverse engineering or recreation, even if the design is just adapted or modified. TEI1000 is protected under such right and in case of plagiarism we will have to do anything necessary in order to protect our assets.

Schematics and other handouts serve for informational purposes only!

	Title: TEI1000		
	A4	Number: TEI1000 AGI11-A	Rev. 02
	Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page 1 of 43
	Filename: Legal Notices Modules.SchDoc		



Title: TEI1000 - Power Diagram		
A3	Number: TEI1000 AGI11-A	Rev. 02
Datum: 2024-06-20	Copyright: Trenz Electronic GmbH	Page 2 of 43
Filename: Power_Diagram.SchDoc		

	1	2	3	4										
A	<table><tr><th>REV</th><th>Description</th><th></th></tr><tr><td></td><td></td><td></td></tr><tr><td>02</td><td> - Changed pulldowns to 1K for all power sequencing groups. Corrected notes about enable thresholds of voltage regulators and load switches. - Changed value for R191-195 to 0R - Added 100pF MAX10 JTAG TCK to GND. Comp. C88 - Removed T6A from Net MAX10_nCONFIG. - Swapped R184 with R186. Upper side 150R, lower side 100R for voltage divider. - Added filtered monitoring of 1.03V power rail by MAX10. - Changed LED D1 to color green. Same like other LEDs. - Fixed group length matching issue of ADD/CMD signals between S10 and first DRAM-Chip. - Replaced RAM-RefClock oscillator (Y1) by 125MHz LVDS oscillator for SX variant and 100MHz LVDS GX variant - Replaced TDM3883 GXB regulator with TDM3885 type - Replaced VCC_CORE voltage regulator by FS1525. 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Connected to AGND: R226.2 (PS-resistor), R225.2 (ADDR-resistor), R222.2 (FB-LS-resistor). - Added 4k99 pull-up (AN 22754) from VCC to ALERT-pin of FS15625 (U12.28) - Added test points to CLKOUT- and ISHRE-pin of FS1525 (U12.29, U12.20) (TP7, TP9) - Replaced R72 by 1k resistor (AN 22752). - Added note about power consumption of 3V3D_PERM-rail. - Added note about purpose of R175. - Added note about slave address and Fsw of FS1525. - Connected unused GXB receiver pins to GND. (U14.(N32, N31, M30, M29, H30, H29, F30, F29, D30, D29, B30, B29)) - Added note about supply voltage range of bank 2K. - Added 0R jumper R235 (AN 22738) between VTT and VREFB2MN0. 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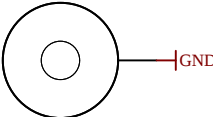
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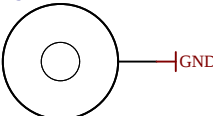
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H1



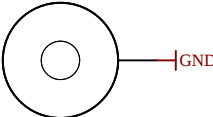
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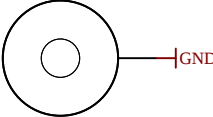
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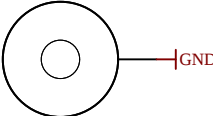
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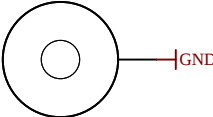
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H2



Mount.Hole 3.2mm für Unterlegscheibe

H4



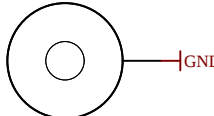
Mount.Hole 3.2mm für Unterlegscheibe

Supported Voltage Ranges:

Power Rail	Direction	Range	Tolerance	Description
VIN	IN	6 - 12V	+10/- 5 %	Main power input
S10_VCCIO_B2K	IN	1.2 - 1.8V	+/- 5 %	FPGA Bank 2A power input. Connect to 1V8D or to external DCDC on carrier card.
1V8D	OUT	1.8V	+/- 3 %	SoM output voltage. Can be used to power FPGA banks or peripherals. Up to 1A
S10_VCCIO3C	OUT	3.3V	+/- 3 %	SoM output voltage. Can be used to power FPGA banks or peripherals. Up to 1A

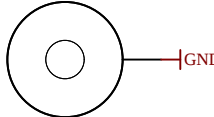
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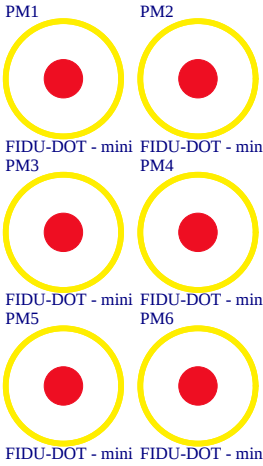


Mount.Hole 3.2mm für Unterlegscheibe

H8



Mount.Hole 3.2mm für Unterlegscheibe



UKCA

UKCA Logo on Top Overlay

UKCA-TOPOVERLAY
MECH1

TE Address Overlay

LOGO ADDRESS
LOGO1

TE Logo PRINT Layer

LOGO PRINT

Serial1
Serial
Serialnumber 6,3 x 6.3mm

Assembly variant	AGI11-A
Created by	VY
Modified by	VY
Modified at	2026-06-25
SVN Revision	19891 [Locally Modified]



Title: TEI1000			
A4	Number: TEI1000 AGI11-A		Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page4 of 43
Filename: TEI1000.SchDoc			

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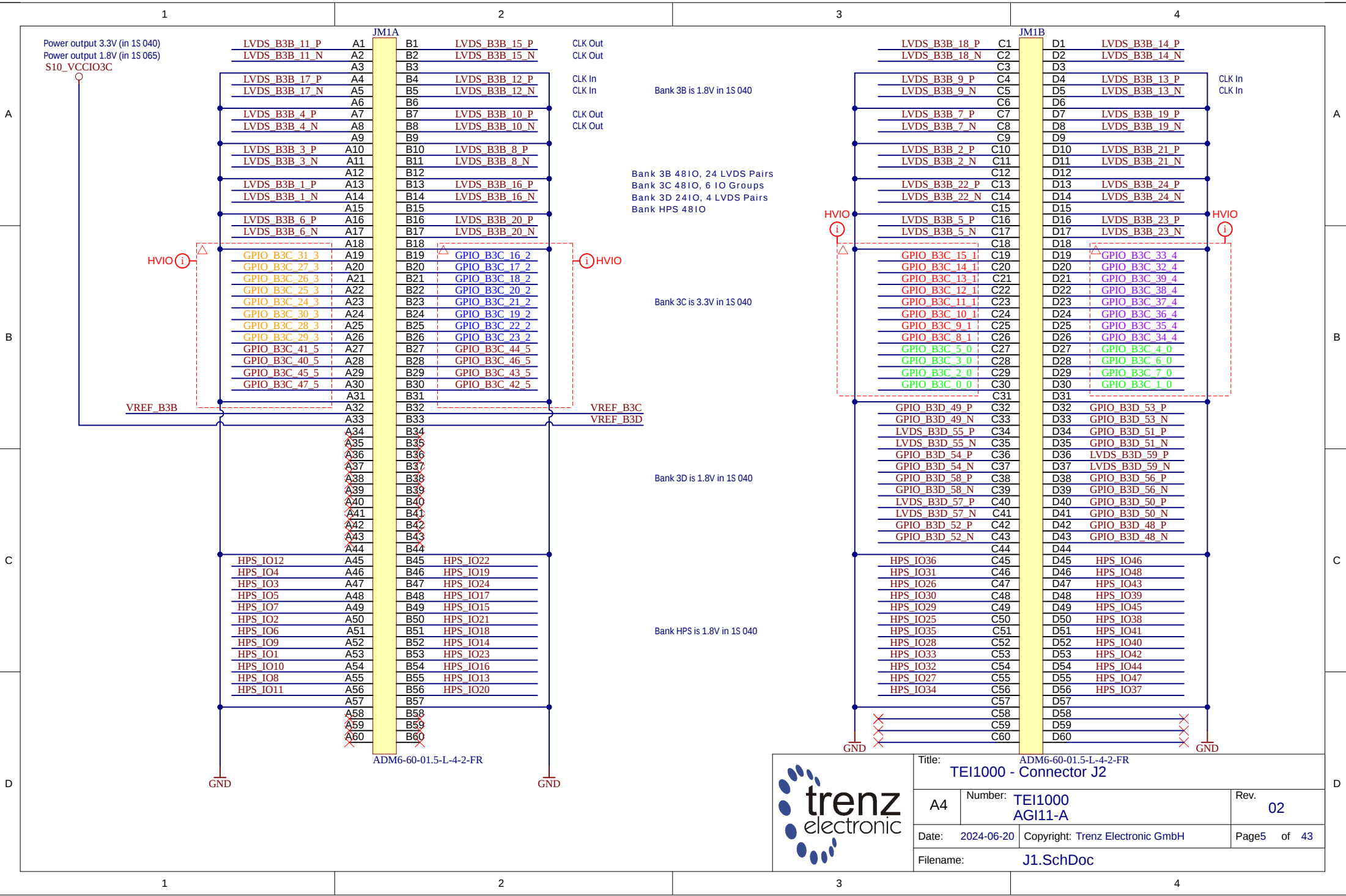
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Title: ADM6-60-01.5-L-4-2-FR
TEI1000 - Connector J2

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AGI11-A

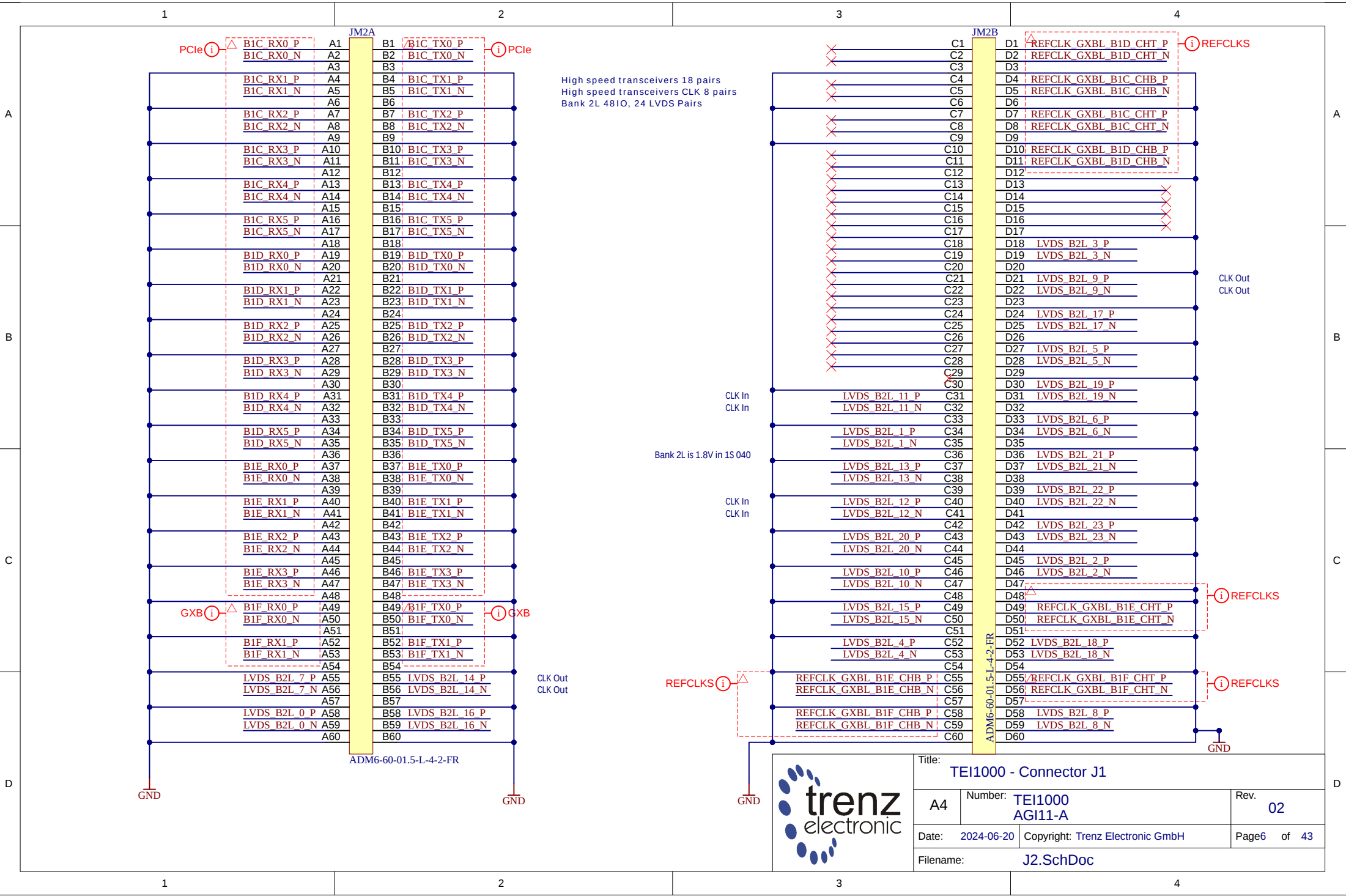
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Date: 2024-06-20

Copyright: Trenz Electronic GmbH

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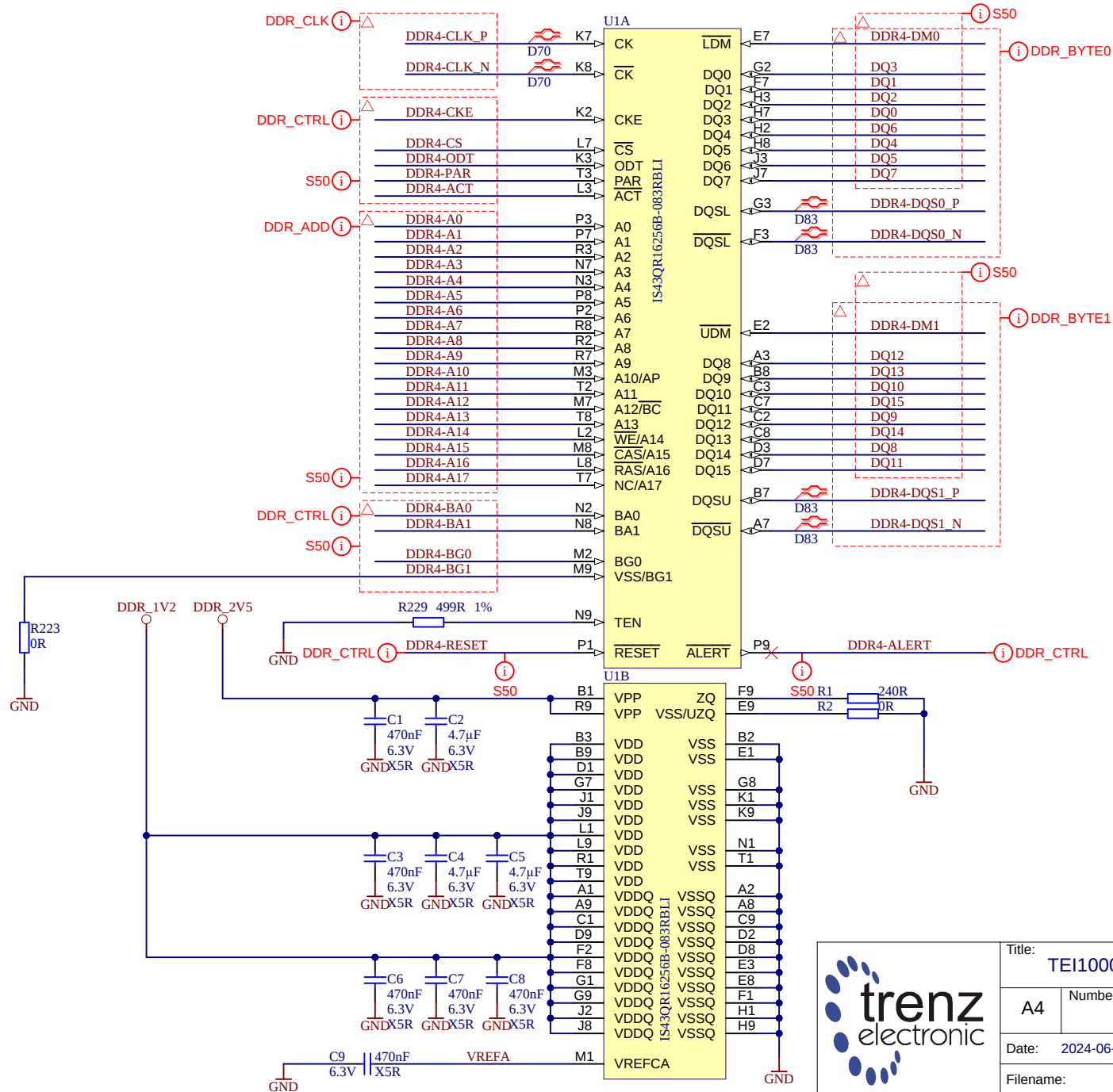
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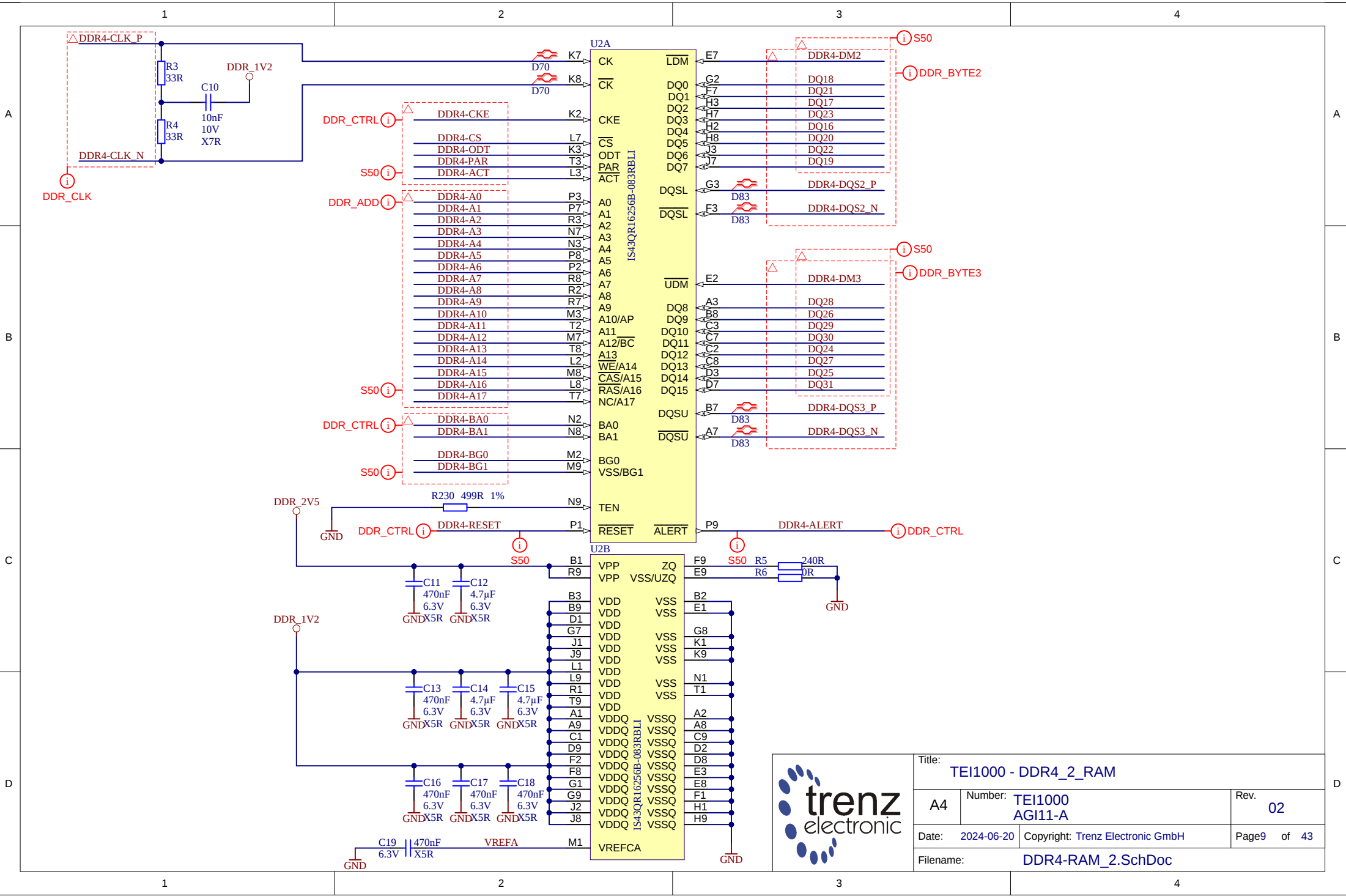
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page 8 of 43
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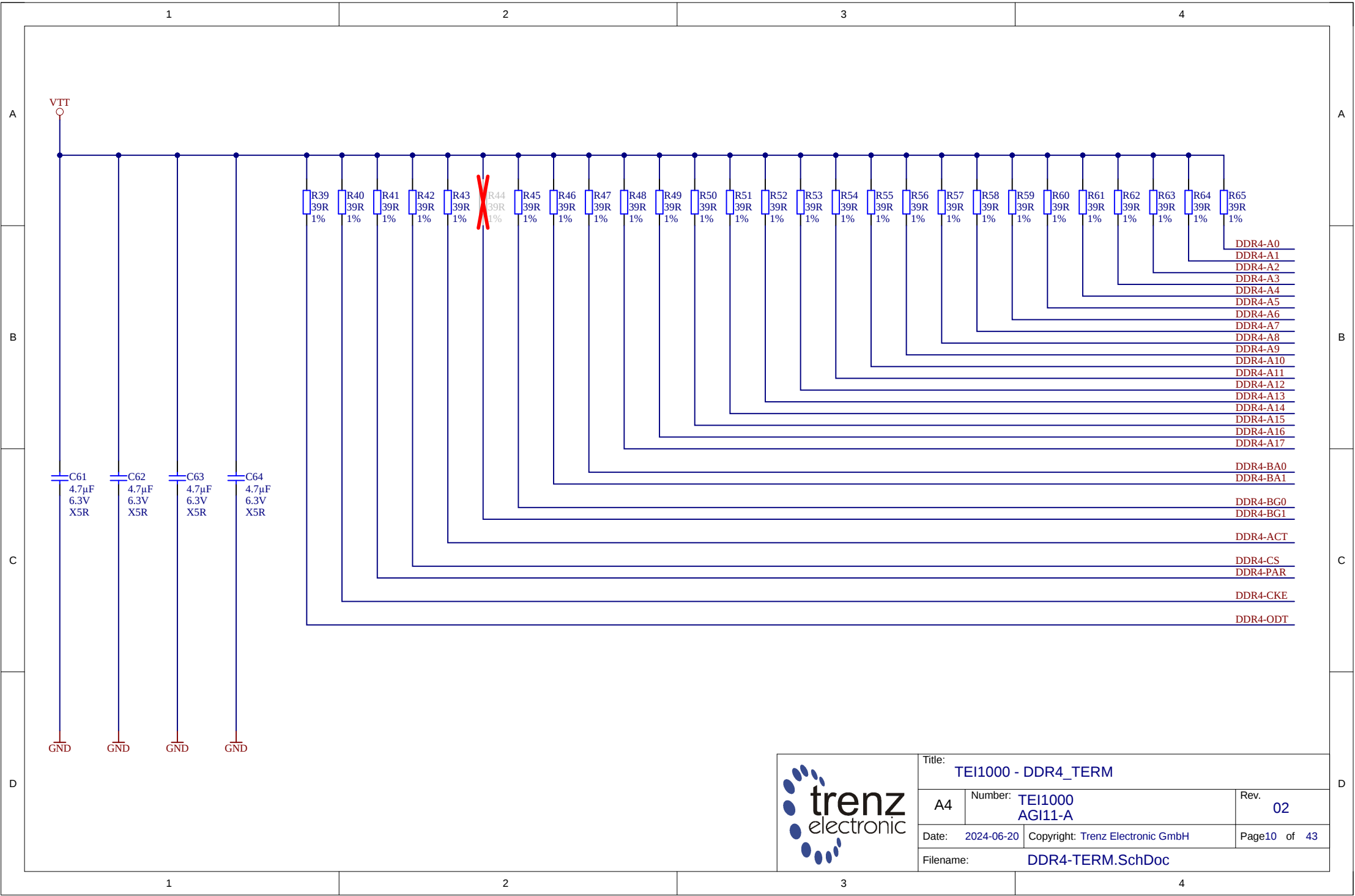
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page 9 of 43
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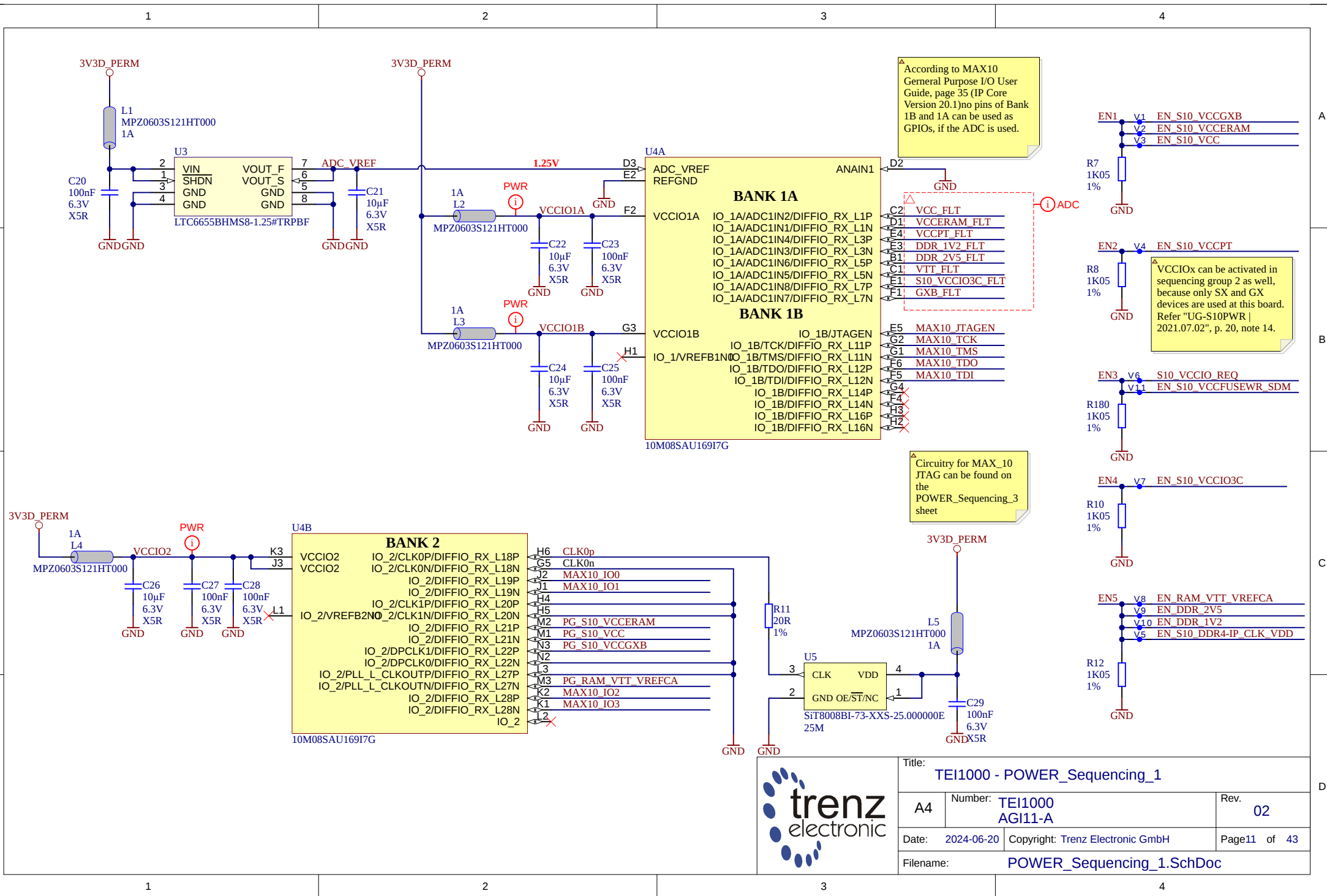
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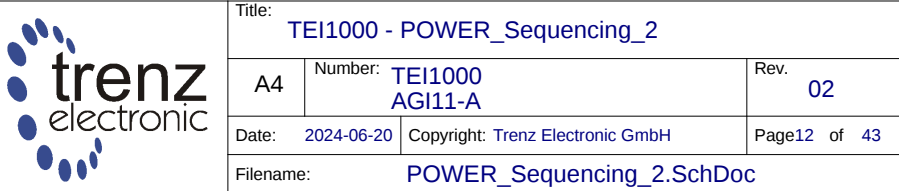
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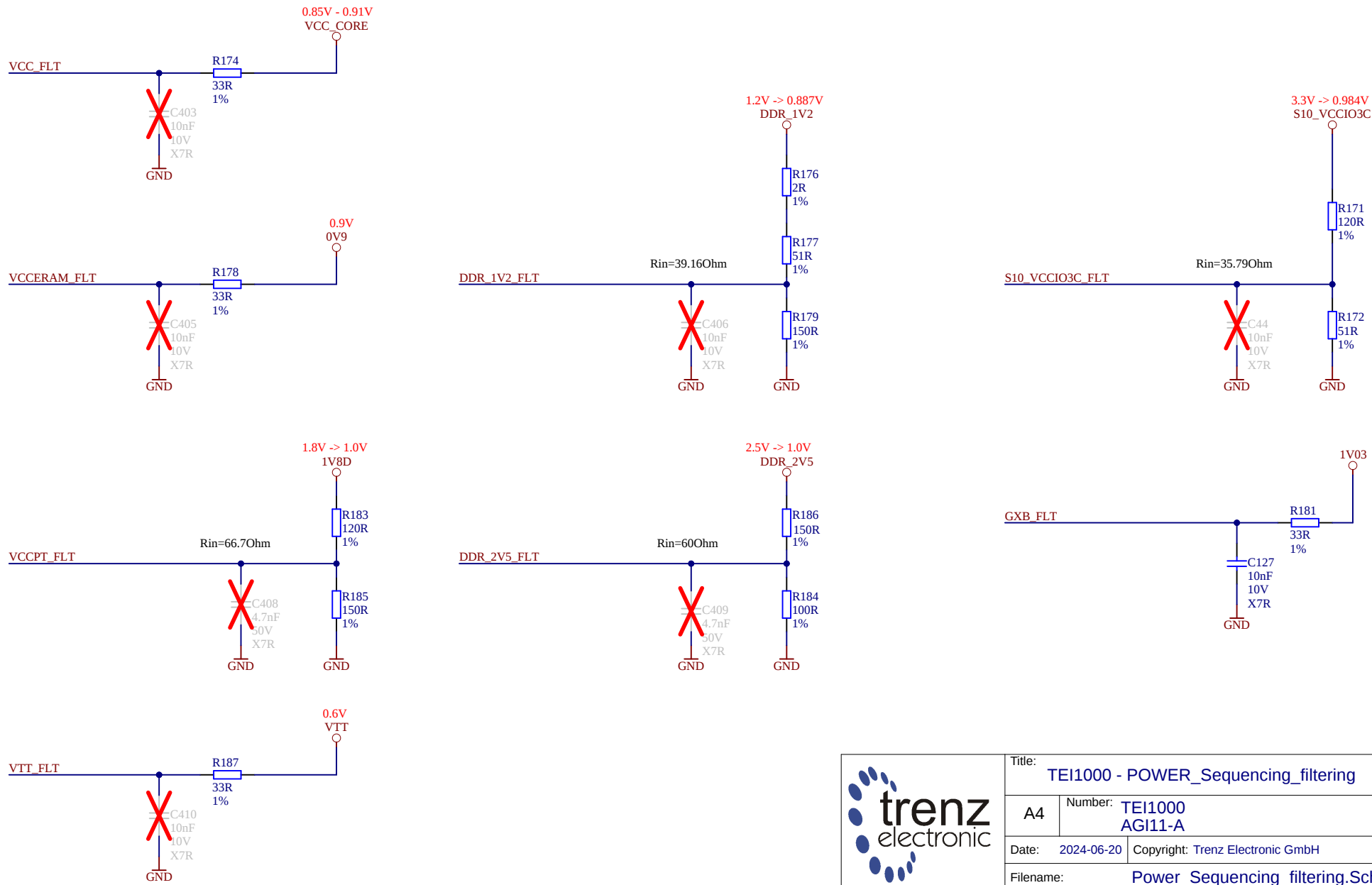
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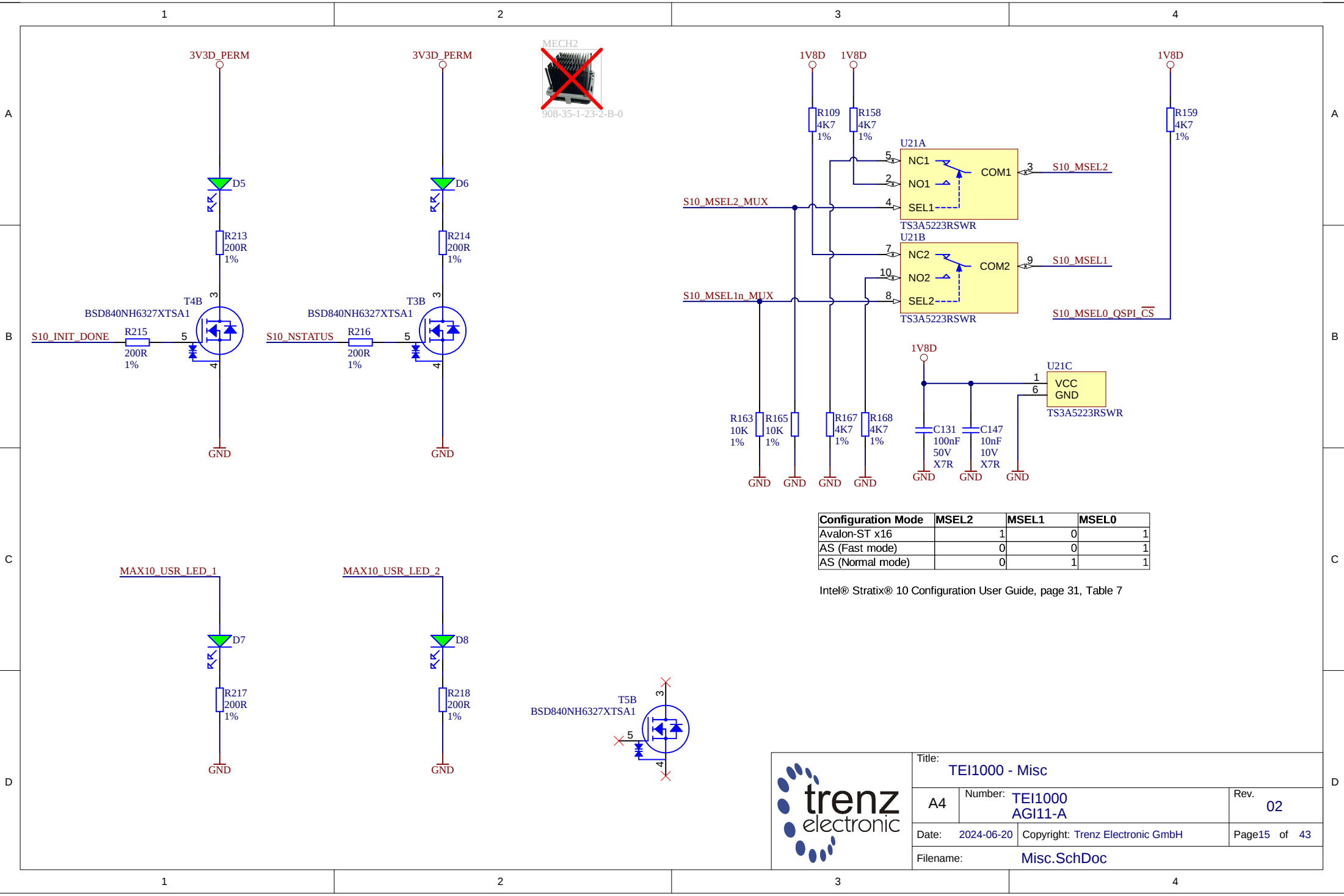








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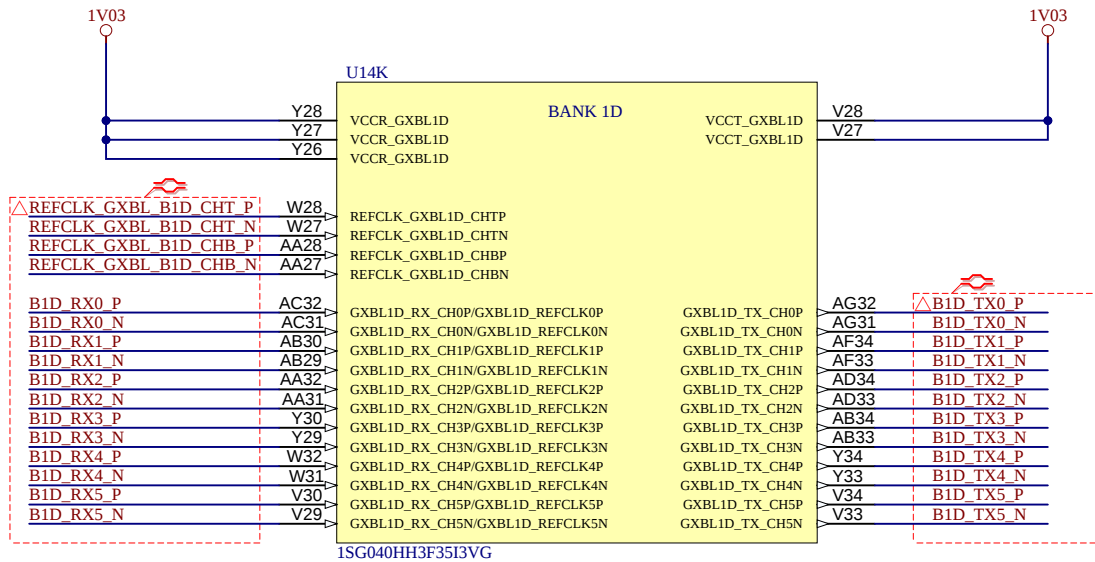
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	A4	Number: TEI1000 AGI11-A
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Rev. 02
Filename: Bank_1D.SchDoc		Page17 of 43

1

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1

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3

4

A

A

B

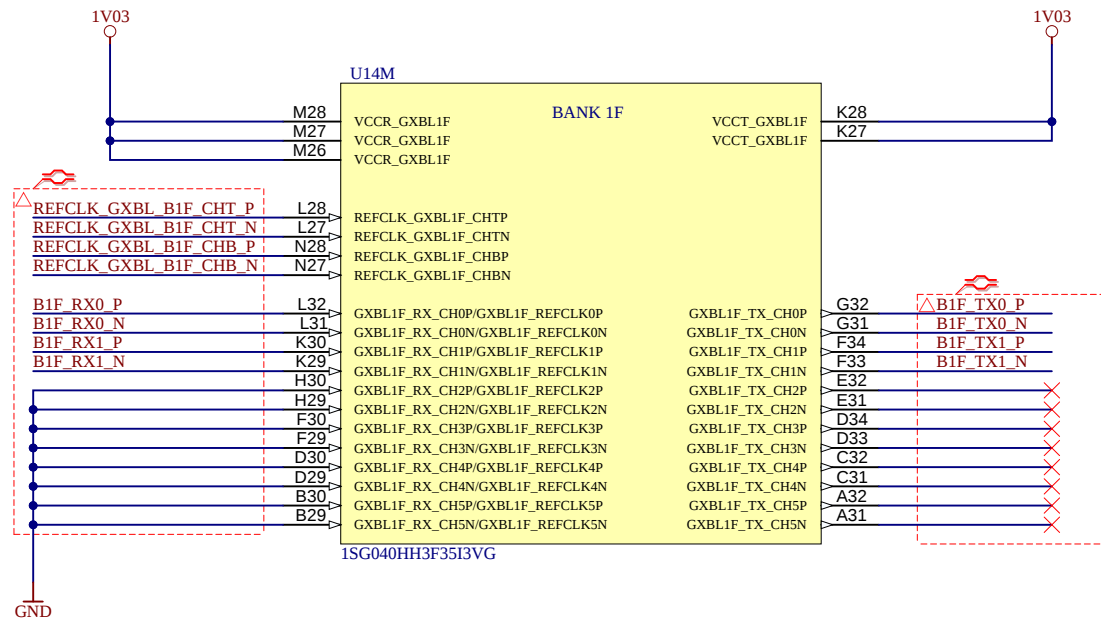
B

C

C

D

D



	Title: TEI1000 - B1F	
	A4	Number: TEI1000 AGI11-A
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Rev. 02
Filename: Bank_1F.SchDoc		Page19 of 43

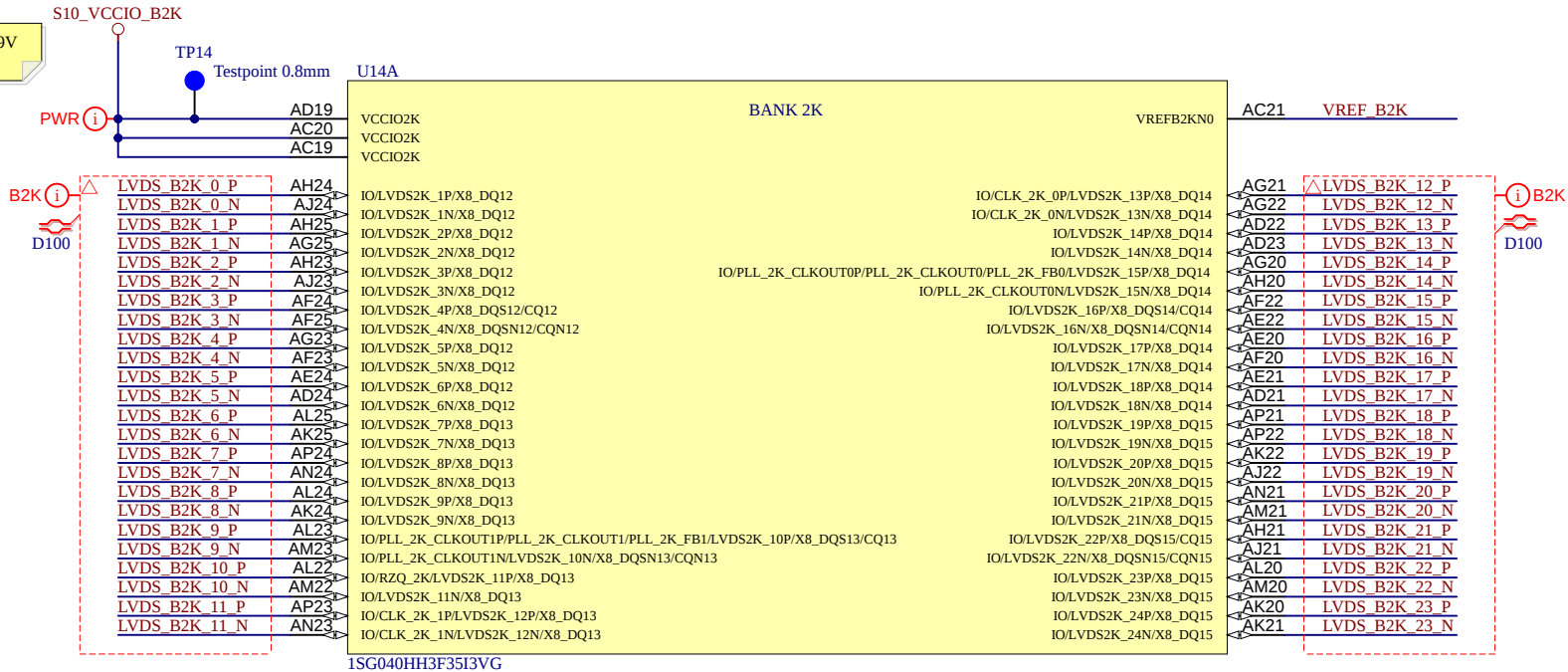
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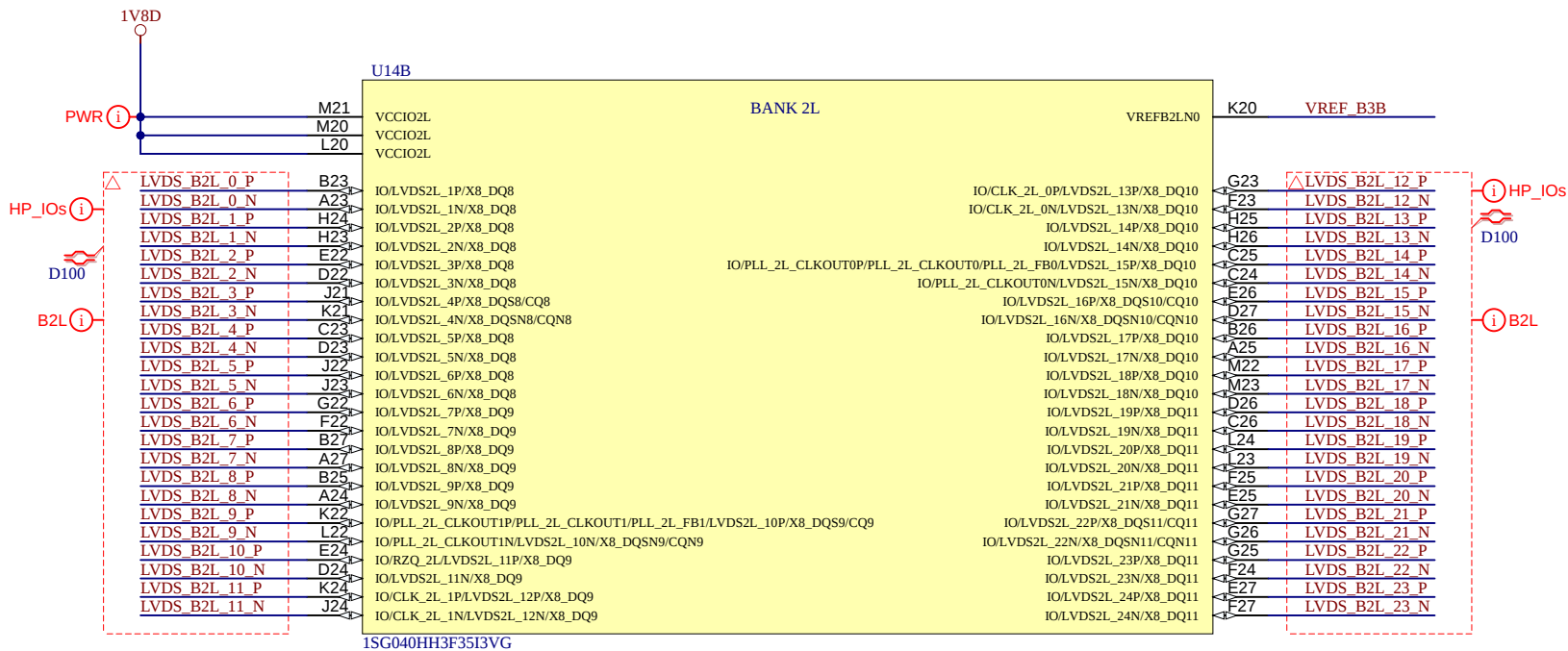
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4

S10_VCCIO_B2K: 1.14 to 1.89V
(S10 datasheet, page 11)



Title: TEI1000 - B2K			
A4	Number: TEI1000 AGI11-A	Rev. 02	
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Filename: Bank_2K.SchDoc			



1

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A

A

B

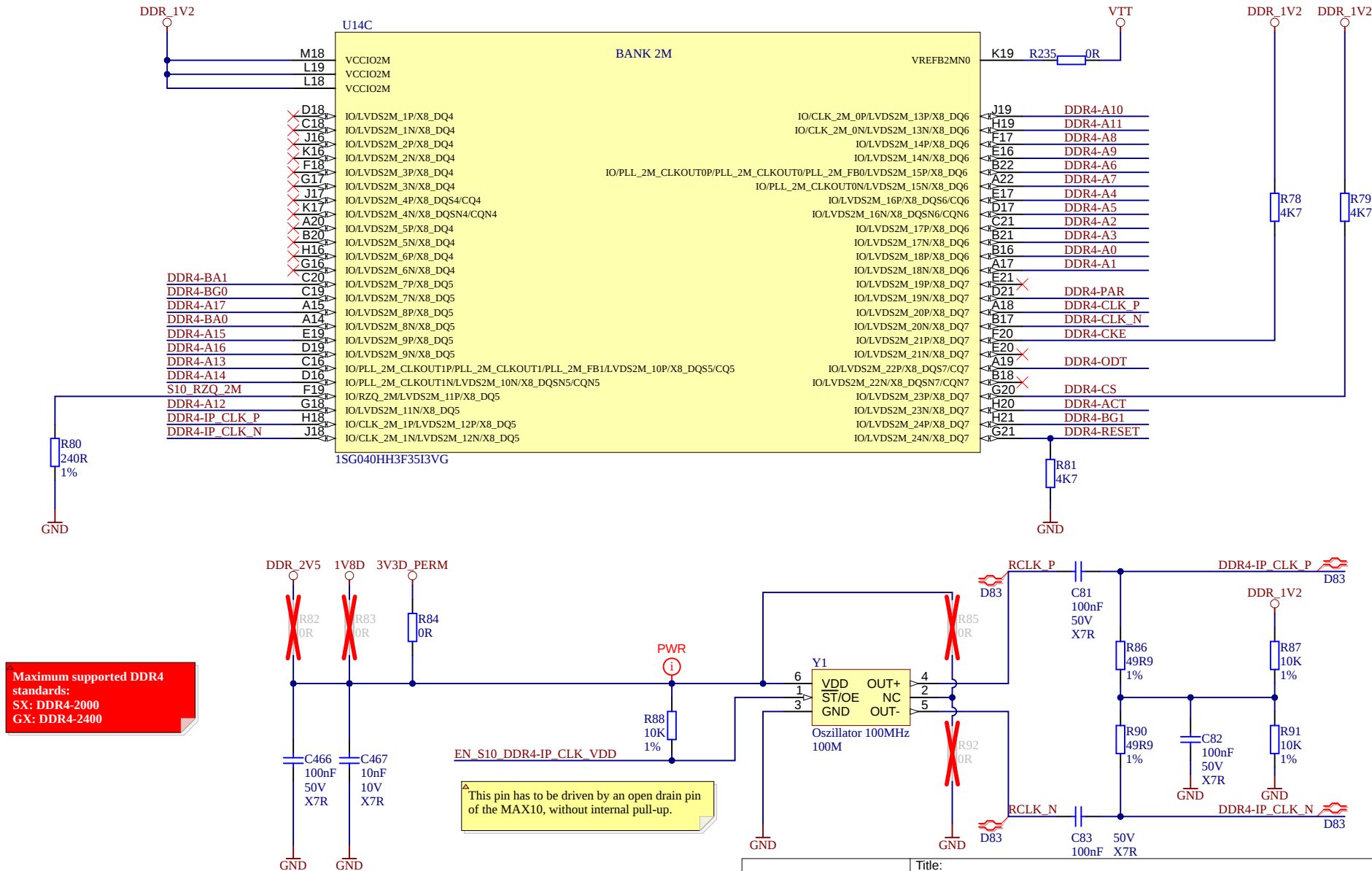
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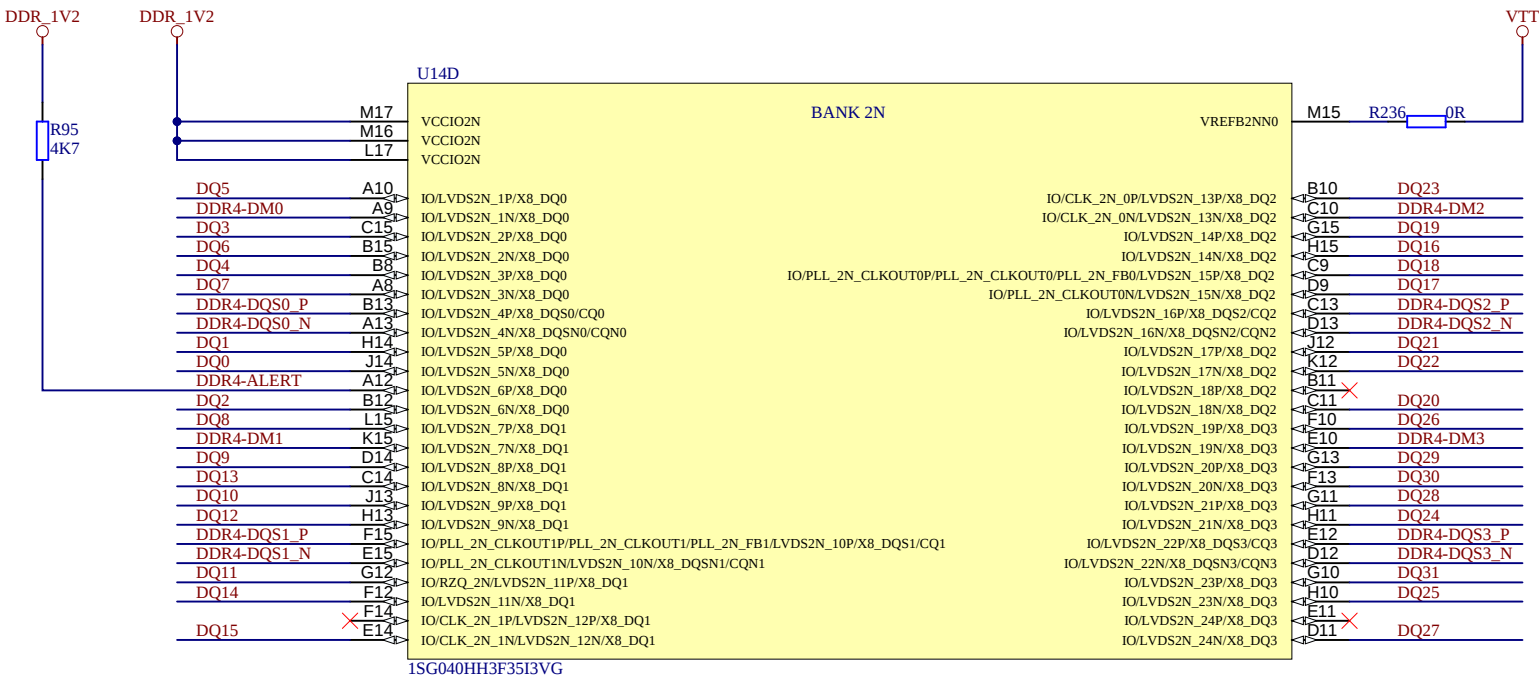
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C

D

D







Title: TEI1000 - B2N		
A4	Number: TEI1000 AGI11-A	Rev. 02
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Filename: Bank_2N.SchDoc		

A

B

C

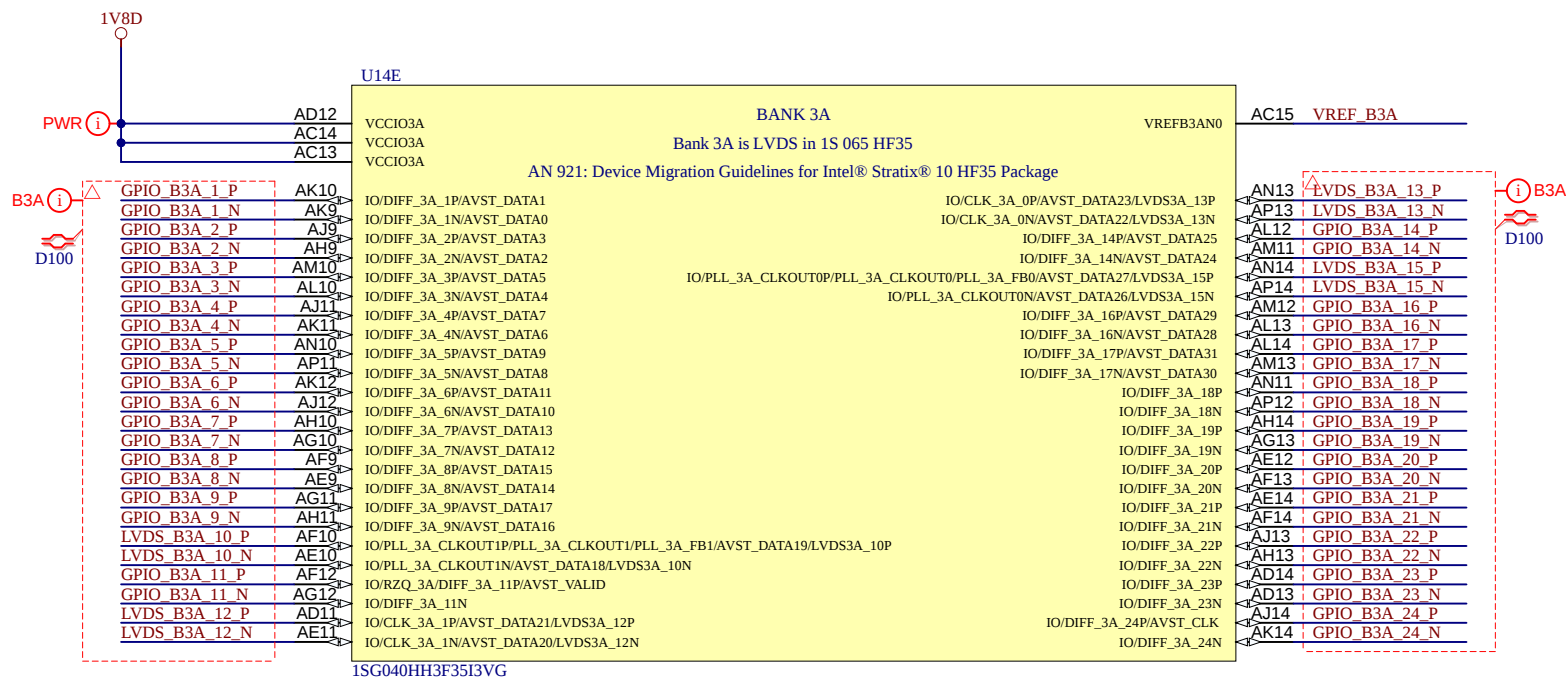
D

A

B

C

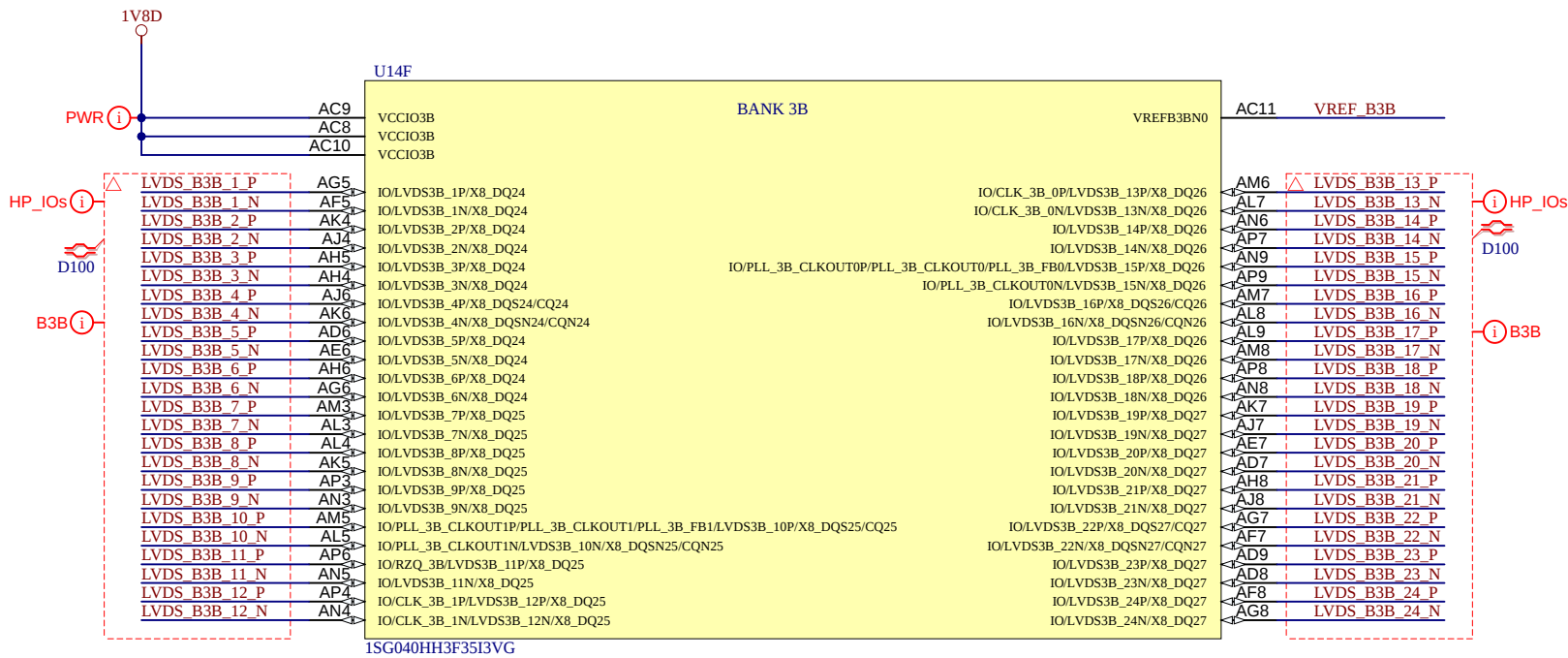
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When I/O bank 3A is used for AVST x16 or AVST x32 configuration mode, you must connect the VCCIO3A power supply to the VCCIO_SDM power supply for proper device functionality.
(Intel® Stratix® 10 Device Family Pin Connection Guidelines, p. 20)



Title: TEI1000 - B3A			
A4	Number: TEI1000 AGI11-A	Rev. 02	
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Filename: Bank_3A.SchDoc			



1

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A

A

B

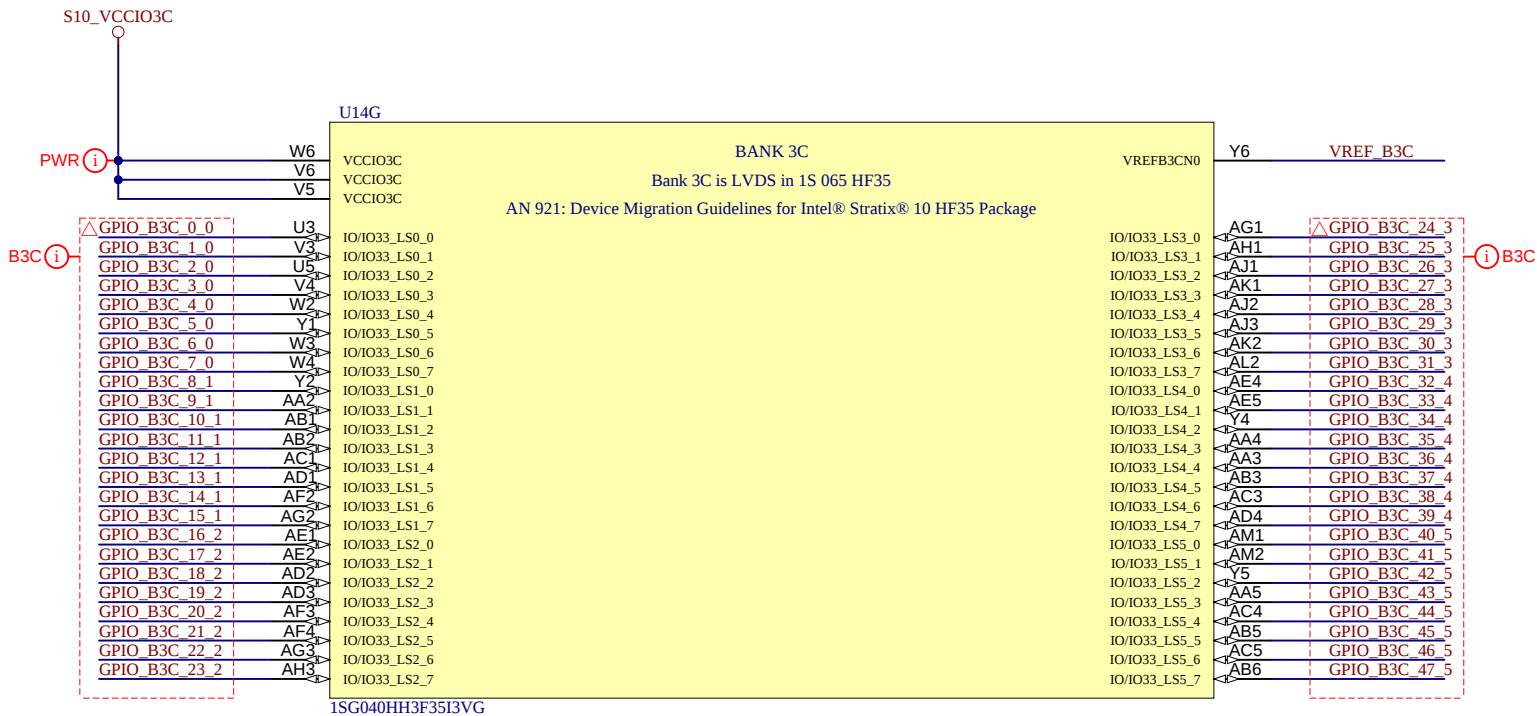
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C

C

D

D



48x high voltage I/Os



Title:TEI1000 - B3C

A4

Number:TEI1000AGI11-A

Rev.02

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Copyright: Trenz Electronic GmbH

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Filename:Bank_3C.SchDoc

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1

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3

4

A

A

B

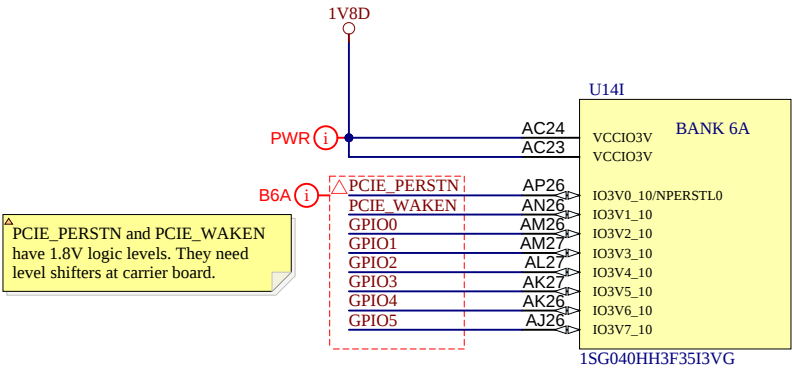
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C

C

D

D



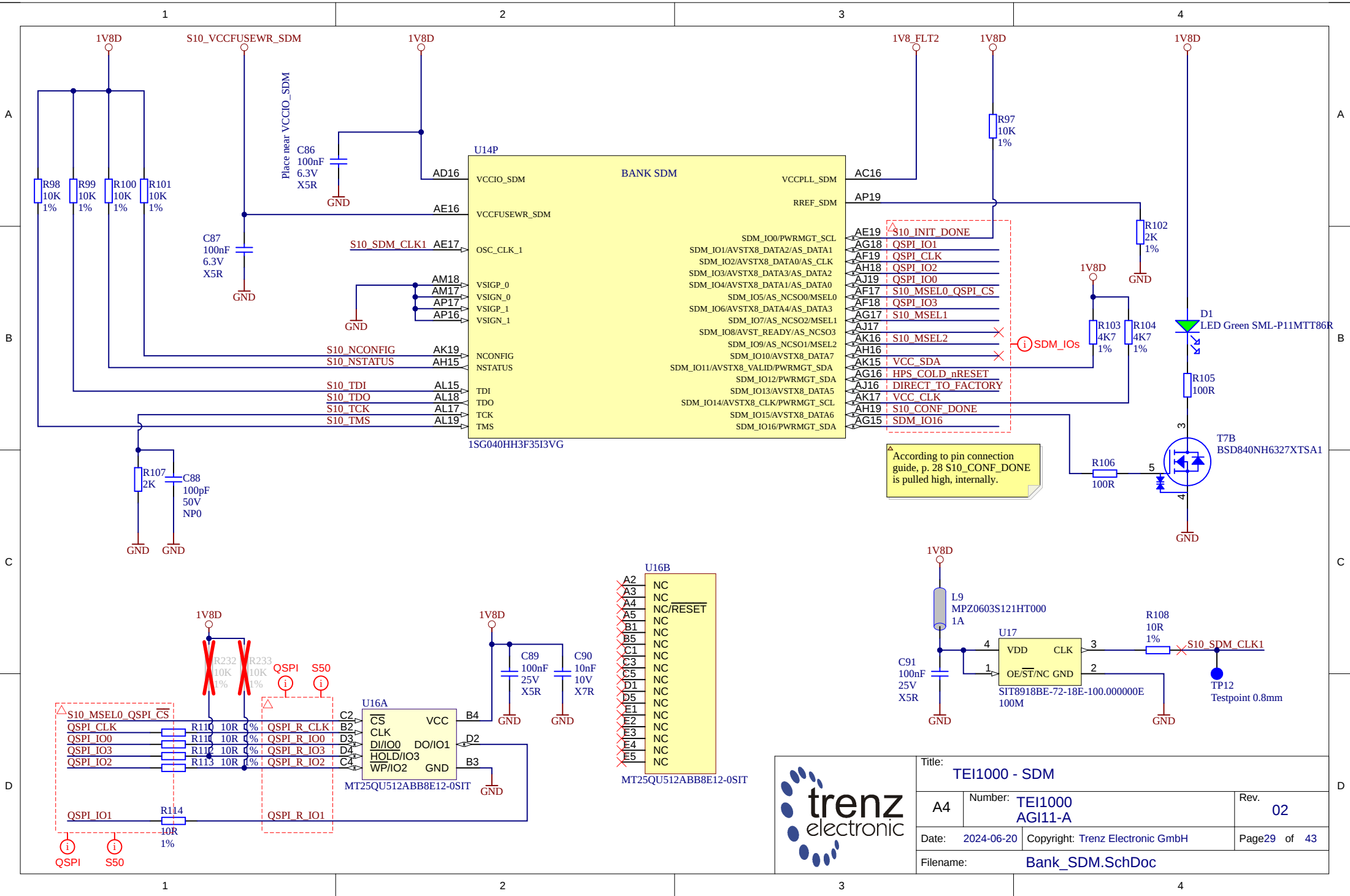
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	A4	Number: TEI1000 AGI11-A
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Rev. 02
Filename: Bank_6A.SchDoc		Page28 of 43

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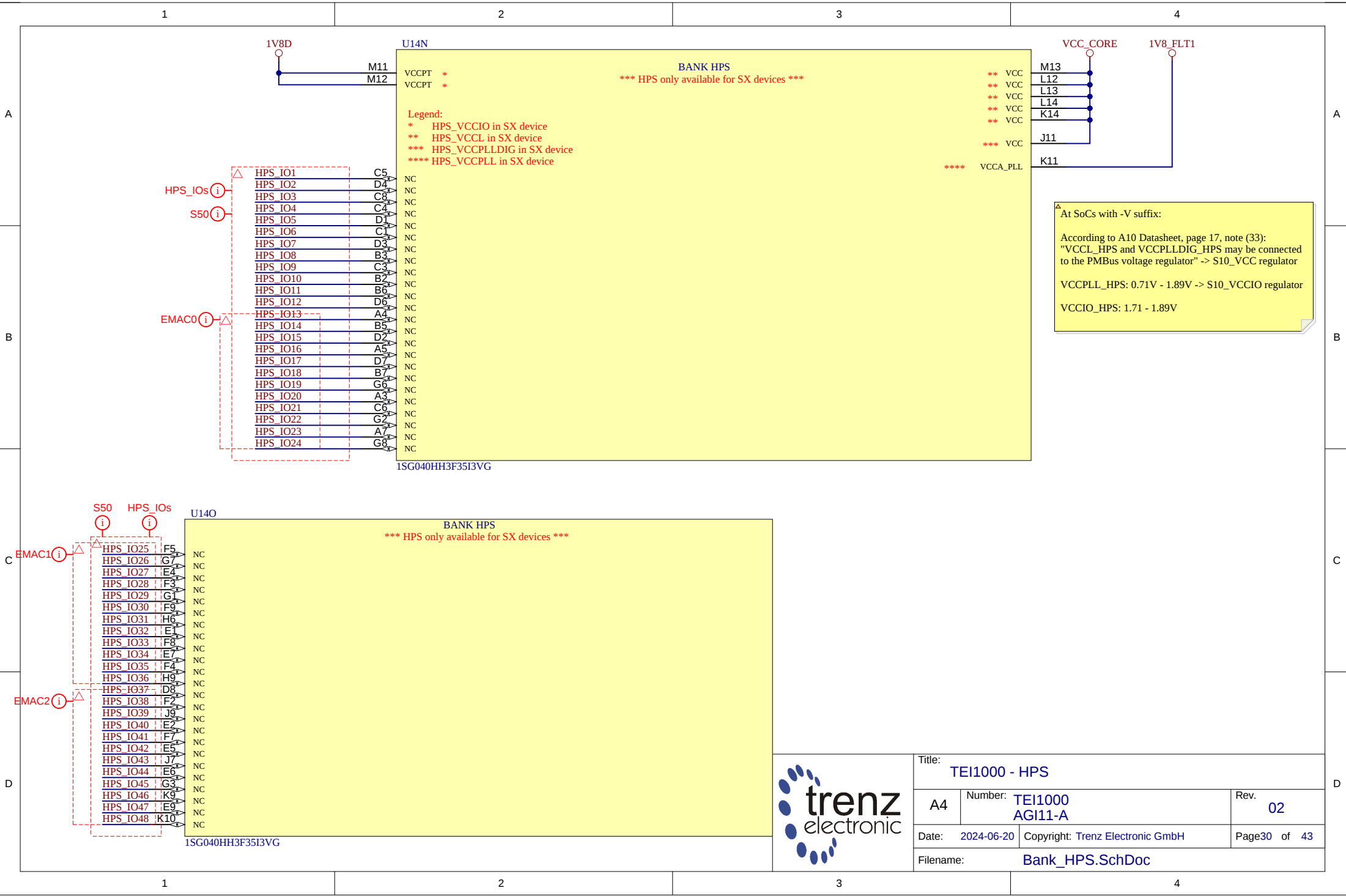
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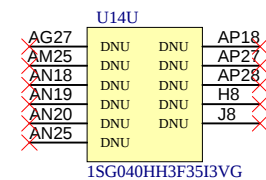
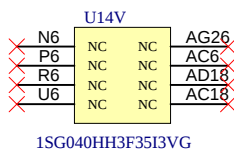
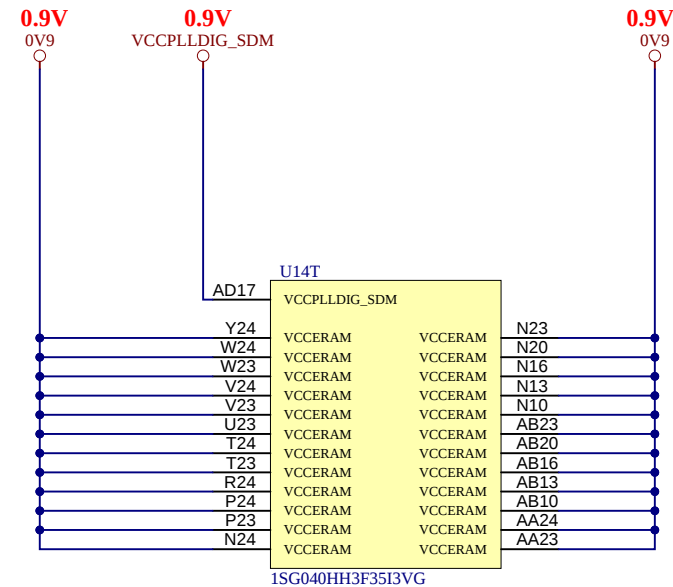
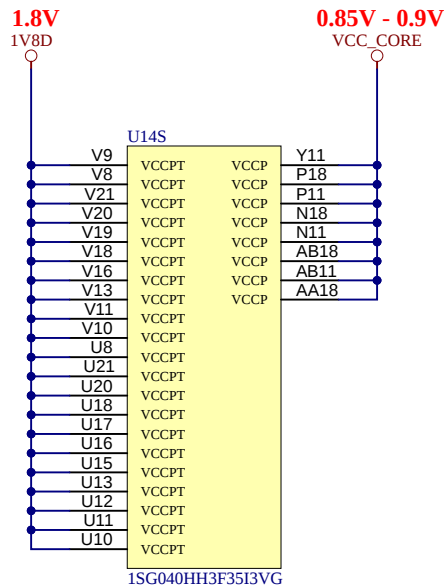
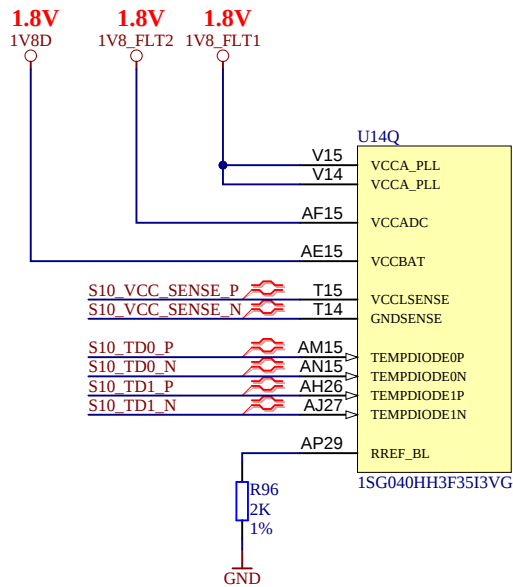
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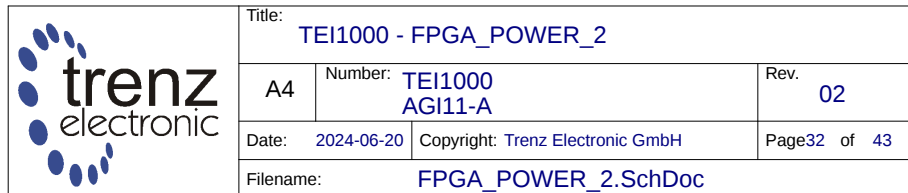


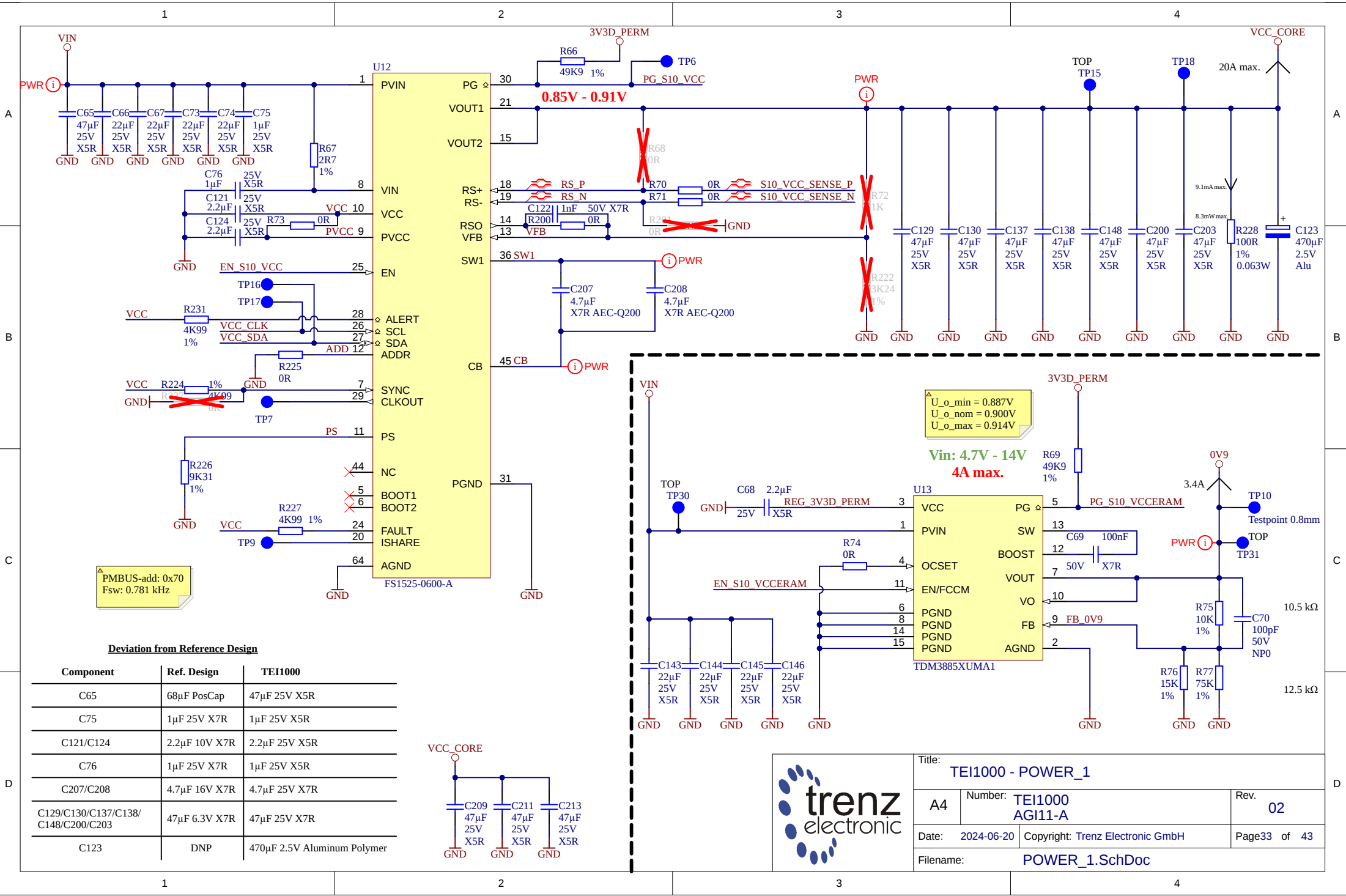
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A4	Number: TEI1000 AGI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page 29 of 43
Filename: Bank_SDM.SchDoc		



Title: TEI1000 - HPS			
A4	Number: TEI1000 AGI11-A		Rev. 02
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Filename: Bank_HPS.SchDoc			



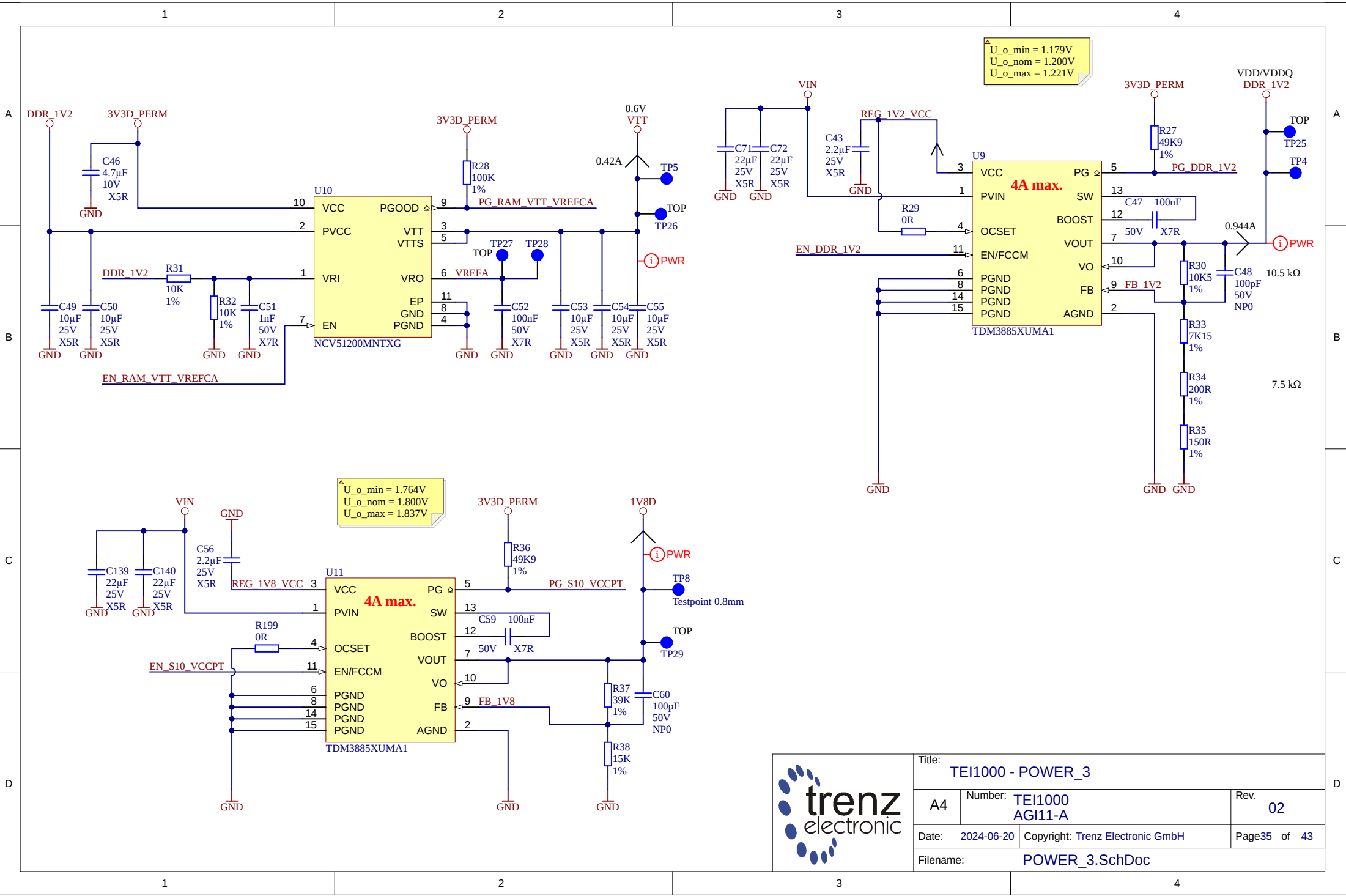




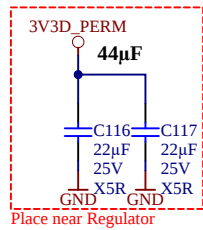
Deviation from Reference Design		
Component	Ref. Design	TEI1000
C65	68µF PosCap	47µF 25V X5R
C75	1µF 25V X7R	1µF 25V X5R
C121/C124	2.2µF 10V X7R	2.2µF 25V X5R
C76	1µF 25V X7R	1µF 25V X5R
C207/C208	4.7µF 16V X7R	4.7µF 25V X7R
C129/C130/C137/C138/C148/C200/C203	47µF 6.3V X7R	47µF 25V X7R
C123	DNP	470µF 2.5V Aluminum Polymer



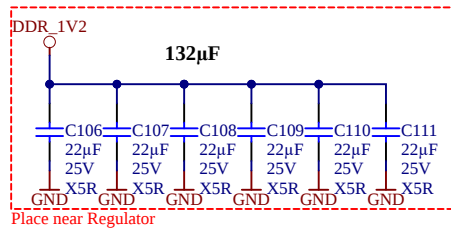
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A4	Number: TEI1000 AGI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page33 of 43
Filename: POWER_1.SchDoc		



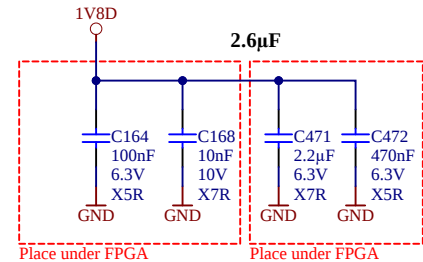
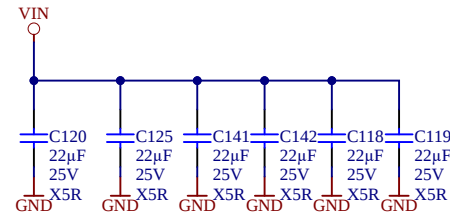
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A4	Number: TEI1000 AGI11-A		Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page35 of 43
Filename: POWER_3.SchDoc			



Place near Regulator



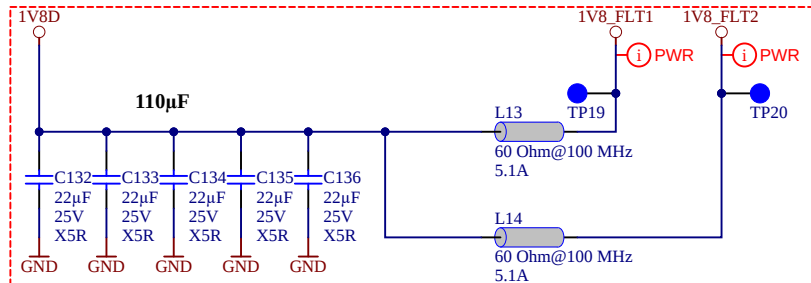
Place near Regulator



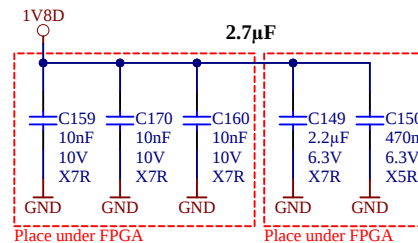
Place under FPGA

Place under FPGA

For supply of bank 6A

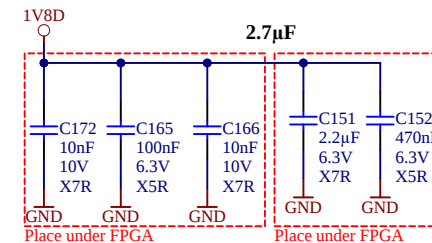


Place near Regulator



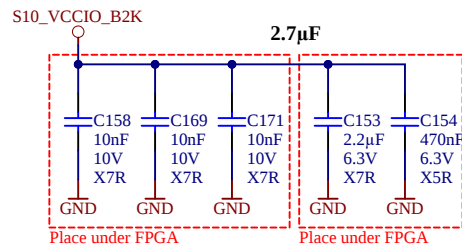
Place under FPGA

For supply of bank 3A



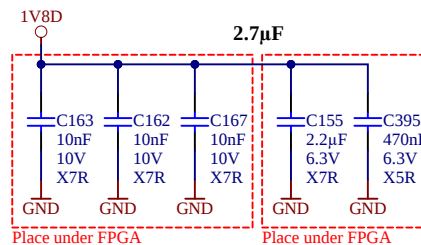
Place under FPGA

For supply of bank 3B



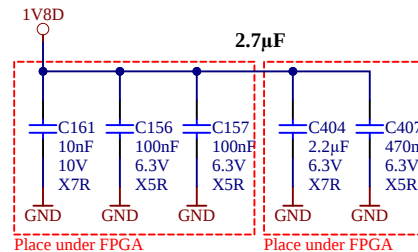
Place under FPGA

For supply of bank 2K



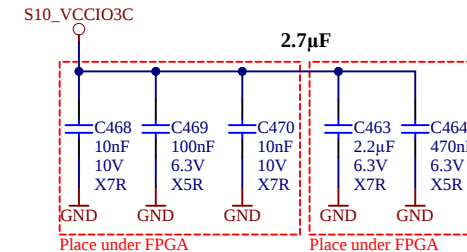
Place under FPGA

For supply of bank 2L



Place under FPGA

For supply of bank 3D



Place under FPGA

For supply of bank 3C



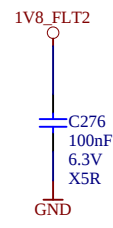
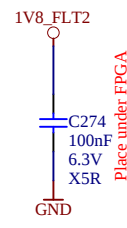
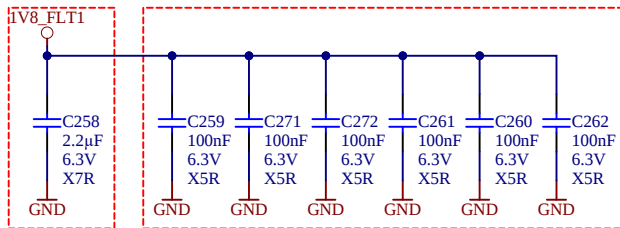
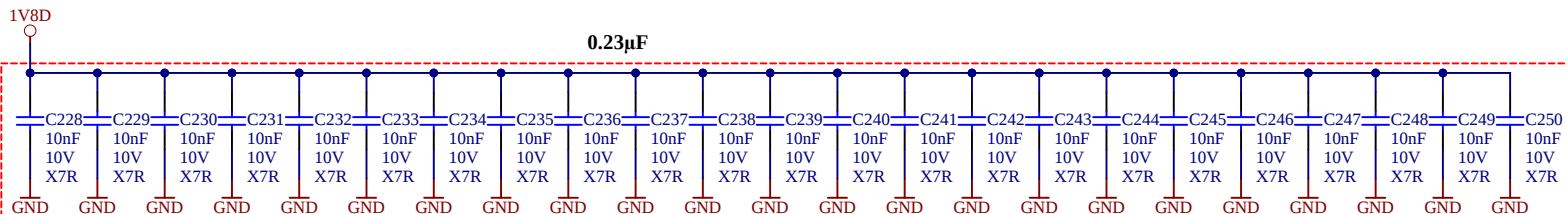
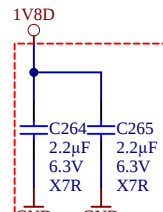
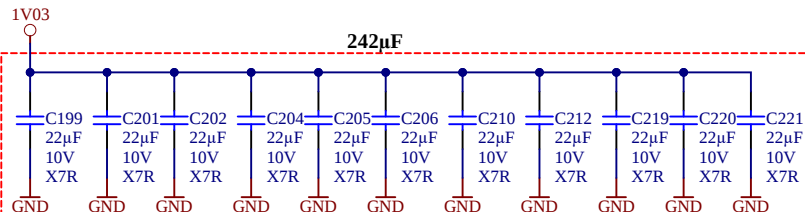
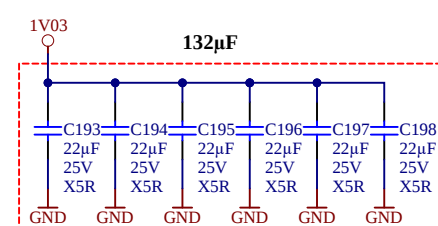
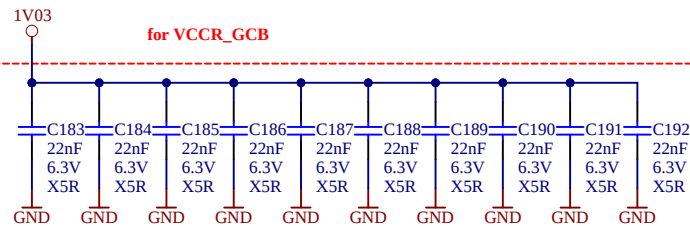
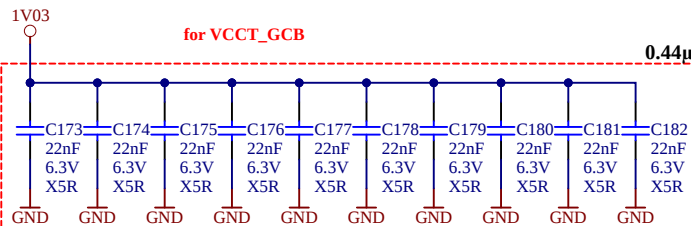
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A4	Number: TEI1000 AGI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page37 of 43
Filename: POWER_Decoupling_1.SchDoc		

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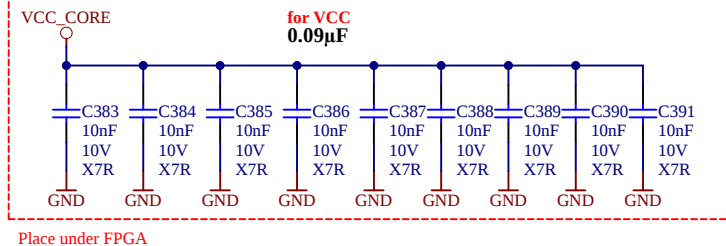
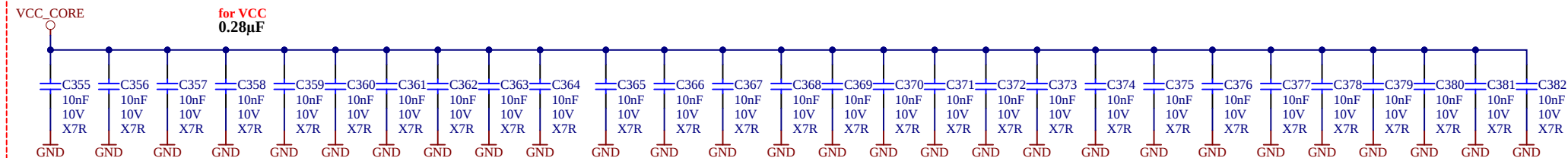
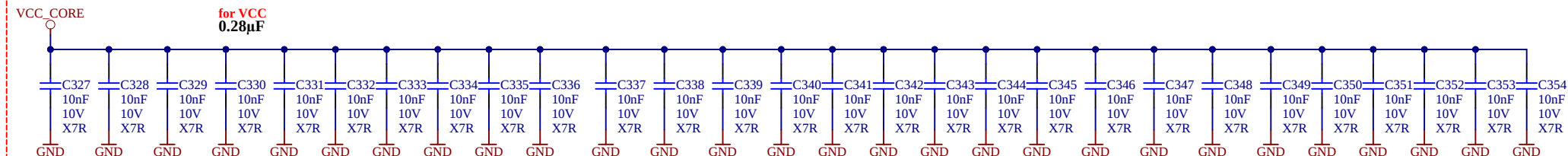
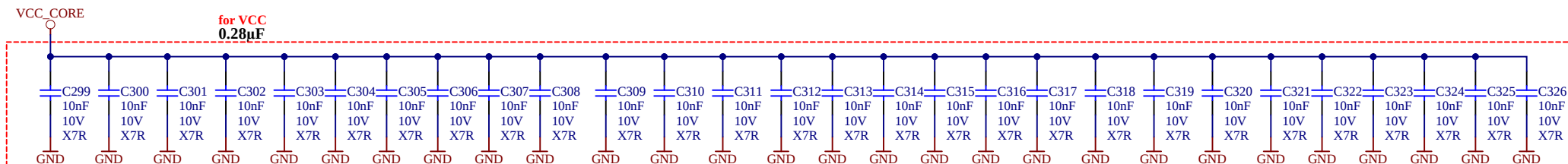
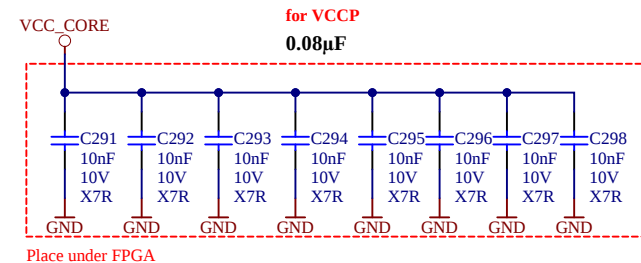
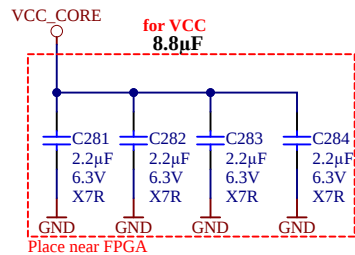
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Filename: POWER_Decoupling_2.SchDoc		

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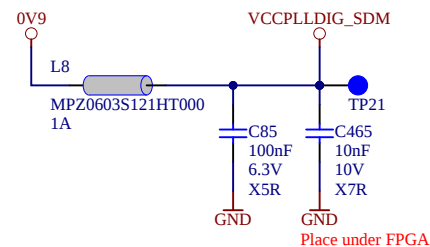
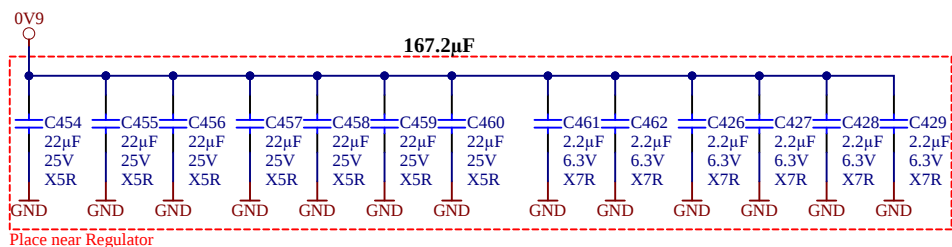
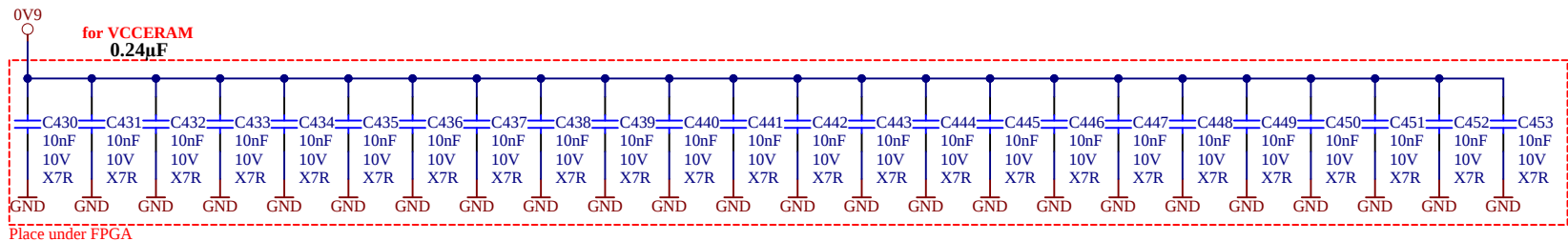
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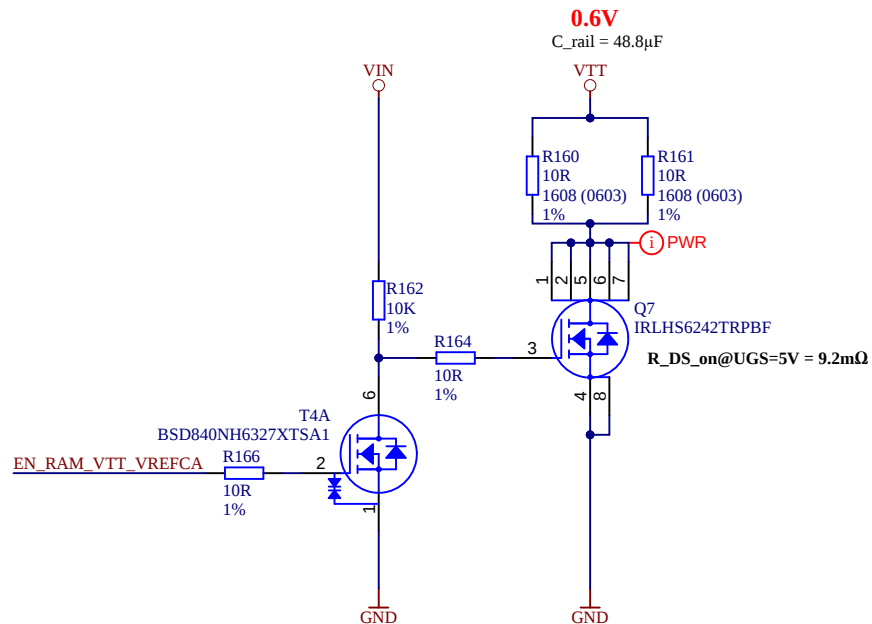
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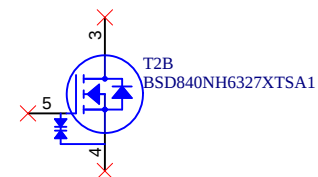
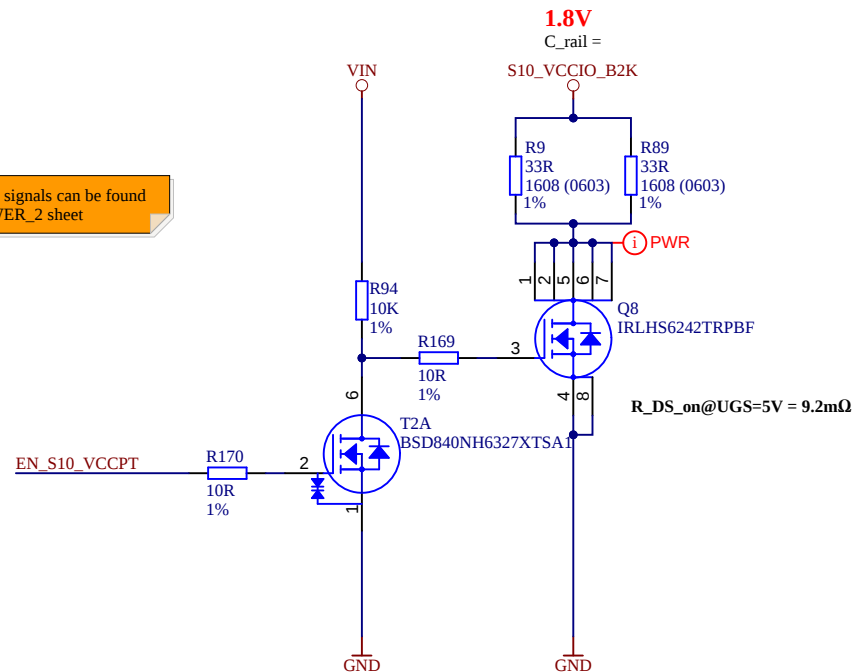
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A4	Number: TEI1000 AGI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page39 of 43
Filename: POWER_Decoupling_3.SchDoc		



	Title: TEI1000 - POWER_Decoupling_3		
	A4	Number: TEI1000 AGI11-A	Rev. 02
	Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page40 of 43
	Filename: POWER_Decoupling_4.SchDoc		



Pull-downs of enable signals can be found on POWER_1 / POWER_2 sheet



	Title: TEI1000 - Discharging_3		
	A4	Number: TEI1000 AGI11-A	Rev. 02
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	Filename: POWER_Discharging_3.SchDoc		